

# High-stability Gyro Sensor: XV7181BB

## Features

- Low angular random walk 0.065  $^{\circ}/\sqrt{h}$  Typ.
- SPI/I<sup>2</sup>C serial interface
- Integrated user-selectable digital filter and notch filter
- Angular rate output (16-bit or 24-bit resolution)
- Embedded temperature sensor
- Wide supply voltage range 2.7 to 3.6 V
- Low power consumption 1.2 mA Typ.
- Rate range  $\pm 460$   $^{\circ}/s$ ,  $\pm 115$   $^{\circ}/s$

## Applications

- Anti-vibration, attitude control for industrial applications
- Autonomous driving equipment such as AGVs and lawn mower

## Typical Performance

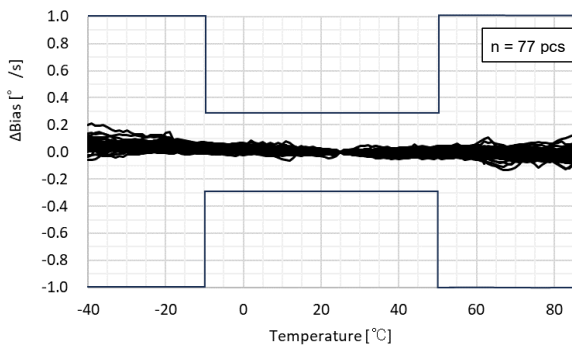


Figure. Bias Variation over Temperature

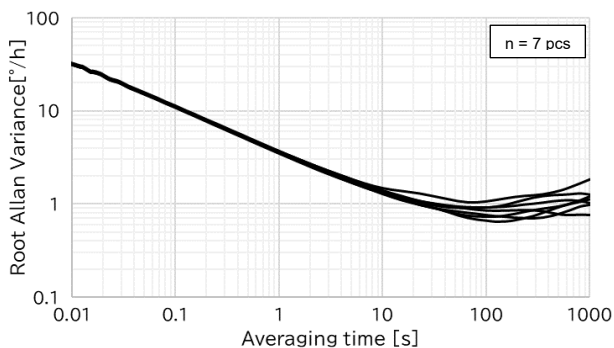
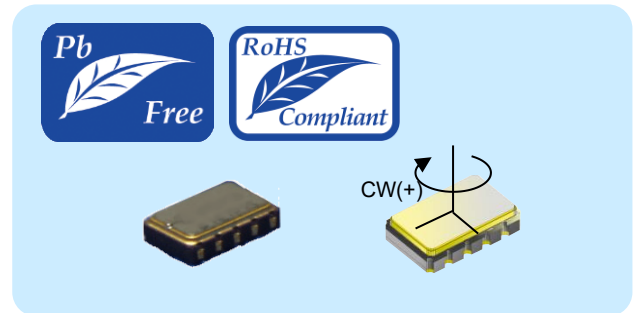


Figure. Allan Variance



## Description

The XV7181BB has superior performance characteristics especially with bias output stability and low noise. Epson achieves these performances by using Epson's original quartz sensor element.

This sensor has digital output interface (SPI and I<sup>2</sup>C) that is compatible with various interface logic levels enabled by interface power supply voltage settings (V<sub>DDI</sub>) that are independent of the main power supply voltage (V<sub>DDM</sub>).

In addition, user-selectable low-pass filters and high-pass filters are available for wide range of cut-off frequencies. The XV7181BB is suitable for various applications from consumer electronics such as wearable devices to industrial equipment.

## Outline Drawing and Terminal Assignment

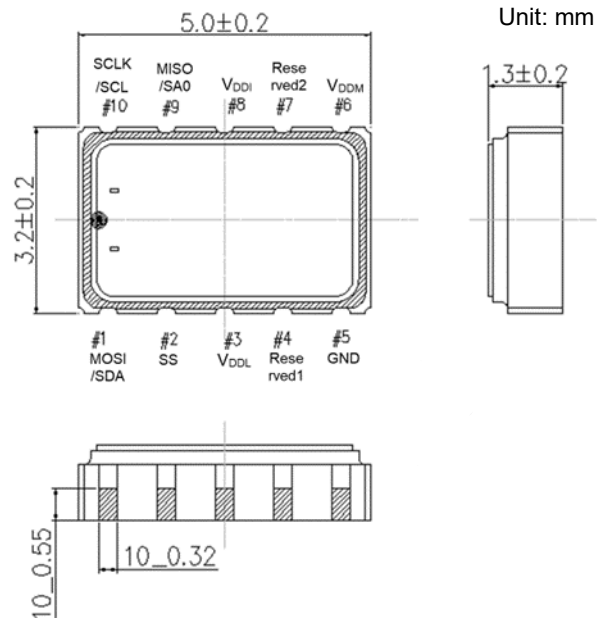


Figure. Outline Dimensions

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**Revision history**

Rev. No.	Date of revision	Page	Revised content
1.0	March. 31, 2024	All	New Release.

**Ordering Information**

Available product codes are shown in a following table.

**Table. Select of the Product Code**





Product code	Product name	Serial interface
X2A0004011002	XV7181BB 51.000kHz F	4-wire SPI, 3-wire SPI, I <sup>2</sup> C

Product name: XV7181BB \*\*.\*kHz \*  
                  ①                  ②                  ③

① Model code ② Frequency ③ Custom recognition

The product code can be identified by a marking on the product. Please refer to Section 4.3. Marking Description for the marking.

**Symbols**

	<ul style="list-style-type: none"> <li>● <b>A lead-free product.</b></li> </ul>
	<ul style="list-style-type: none"> <li>● <b>Compliant with the EU RoHS directive.</b> * About products without the Pb-Free label Product terminals are lead-free but the internal components of the product contain lead (high melting point solder lead as well as the lead contained in the glass of an electronic component are both not applicable under the EU RoHS directive).</li> </ul>
	<ul style="list-style-type: none"> <li>● <b>Indicates a product intended for use in an automobile (body, information systems, etc.). The product has been designed and manufactured in accordance with a quality assurance program suited for the on-board environment of an automobile.</b></li> </ul>
	<ul style="list-style-type: none"> <li>● <b>Indicates a product intended for use to further the safe operation of an automobile (driving, stopping, turning). The product has been designed and manufactured in accordance with a quality assurance program suited for the on-board safety of an automobile.</b></li> </ul>

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### 1. Block Diagram

The block diagram of the sensor is shown in Figure 1.1.

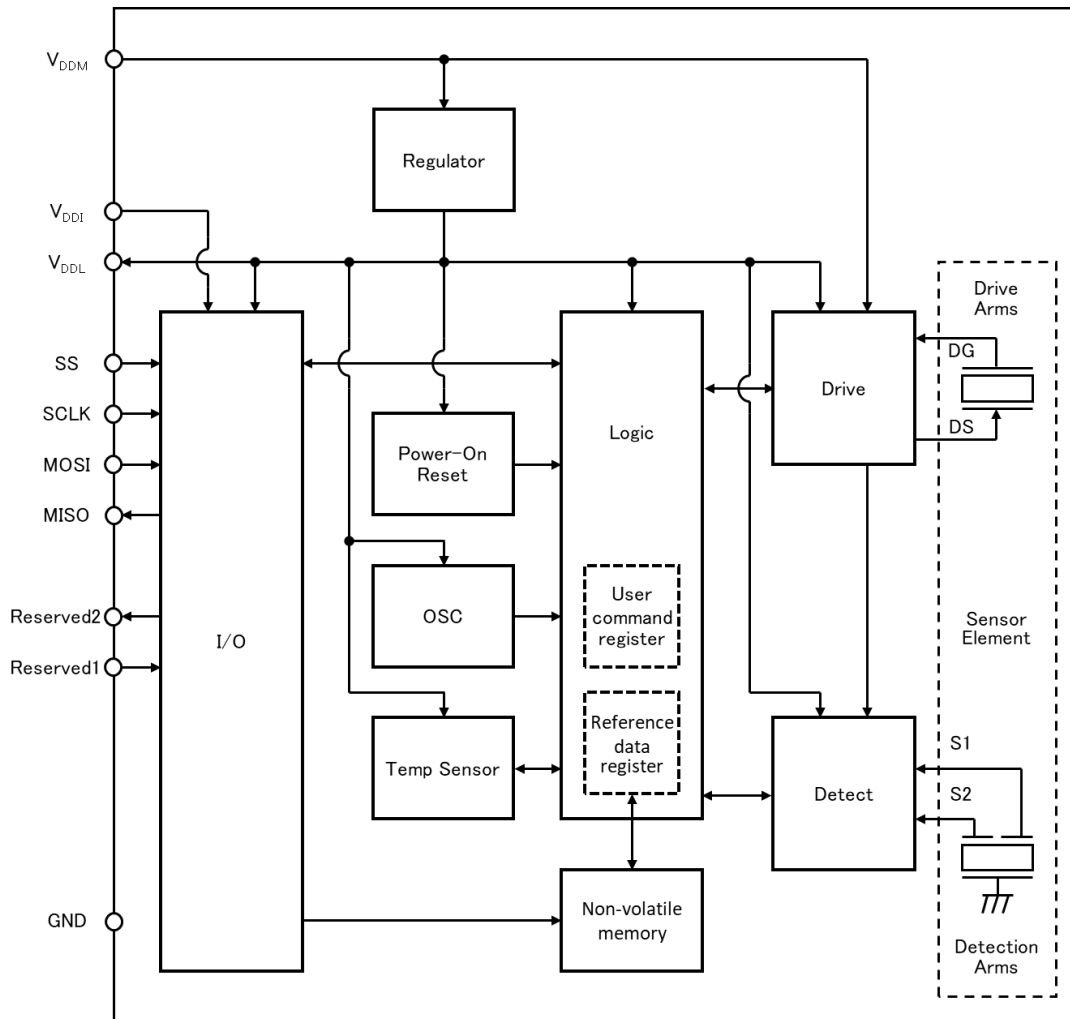


Figure 1.1 Functional Block Diagram

## 2. Function Explanation

### 2.1. Detection Axis and Output Polarity

This product detects an angular rate of a rotational movement. The correlation between a detecting axis of the angular rate and an output polarity is shown in Figure 2.1.

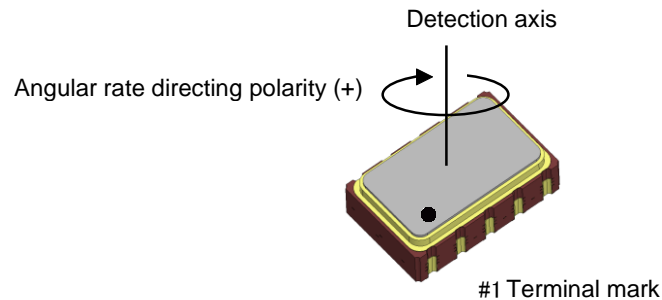


Figure 2.1 Detection Axis and Detection Polarity

### 2.2. Interface

This product is compatible with SPI (4-wire, 3-wire) and I<sup>2</sup>C. This sensor allows for interface power supply voltage settings ( $V_{DDI}$ ) that are independent of the power supply voltage ( $V_{DDM}$ ) to enable communications with interfaces of various logic levels.

### 2.3. Angular Rate Output

The angular rate output data is provided in the 2's complement expression. 16 bits or 24 bits can be selected from the register settings. The AD converter sampling frequency  $f_s$  is 12.000 kHz for frequency symbol  $J_{\pm}$ .

The angular rate output data can also be provided after processing through the Low-Pass Filter (LPF). In addition, the Notch Filter (NF) is available and can be enabled to suppress residual output of detuning frequency after mechanical shock. Regarding the Digital Filter, See the Chapter 8.

LPF: This is a 2<sup>nd</sup>, 3<sup>rd</sup> or 4<sup>th</sup> order filter, the cutoff frequency can be selected.  
(1/10/25/50/100/200/400/500 [Hz])

NF: Either enable or disable can be selected. The center frequency of the Notch Filter is already set at our factory individually.

### 2.4. Temperature sensor output

Temperature output data is provided in the 2's complement expression. The temperature output in the zero code can be selected by the register setting. See the Sector 6.5.

### 3. Electrical Characteristics

#### 3.1. Absolute Maximum Rating

**Table 3.1 Absolute Maximum Ratings**

Parameter	symbol	Min.	Type.	Max.	unit	Condition
Supply voltage	V <sub>DDM</sub>	-0.3	-	+4.0	IN	GND = 0 V
Supply voltage for interface	V <sub>DDI</sub>	-0.3	-	+4.0	IN	GND = 0 V
Storage temperature	T <sub>STG</sub>	-40	-	+85	°C	
Conditions for soldering	-	+350 °C, 3 s			-	

#### 3.2. Operating Conditions

**Table 3.2 Operating conditions**

Parameter	Symbol	Min.	Type.	Max.	Unit	Condition
Supply voltage	V <sub>DDM</sub>	+2.7	-	+3.6	IN	GND = 0 V
Supply voltage for interface	V <sub>DDI</sub>	+1.65	-	+3.6	IN	GND = 0 V
Operating temperature	T <sub>OPR</sub>	-40	-	+85	°C	
Supply voltage start-up time	t <sub>pu</sub>	0.01	-	100	ms	V <sub>DDM</sub> 0 % to 90 %
4-WireSPI clock frequency	f <sub>SCLK</sub>	-	-	10	MHZ	V <sub>DDI</sub> > +2.4 V
4-WireSPI clock frequency	f <sub>SCLK</sub>	-	-	5	MHZ	IN <sub>DDI</sub> ≤ +2.4 V
3-WireSPI clock frequency	f <sub>SCLK</sub>	-	-	5	MHZ	
I <sup>2</sup> C clock frequency	f <sub>SCL</sub>	-	-	400	KHZ	
Sampling frequency	f <sub>s</sub>	-	12.000	-	KHZ	Frequency code: J

(Note) Using the drive frequency integral multiplier as communications clock may result in fluctuations in the angular rate output.

(Note) Acquiring angular rate data as a frequency that is a fraction of the integer for the drive frequency can result in fluctuations in the angular rate output.

#### 3.3. DC Characteristics

**Table 3.3 DC Characteristic**

(V<sub>DDM</sub> = 2.7 V to 3.6V, V<sub>DDI</sub> = 1.65 V to 3.6 V, GND = 0 V, T<sub>OPR</sub> = -40 °C to +85 °C)

parameter	symbol	Min.	Type.	Max.	Unit	Condition
Logic input voltage	V <sub>IH</sub>	V <sub>DDI</sub> × 0.7	-	-	V	
	IN <sub>THE</sub>	-	-	V <sub>DDI</sub> × 0.3	V	
Logic output voltage	V <sub>OH</sub>	V <sub>DDI</sub> - 0.4	-	-	V	V <sub>DDI</sub> = Min., Load +1 mA
	IN <sub>OL</sub>	-	-	+0.4	V	V <sub>DDI</sub> = Min., Load -1 mA

3.4. Operating Sequence at Start-Up

Table 3.4 Operating Sequence at Start-Up

$V_{DDM} = 2.7\text{ V to }3.6\text{ V}$ ,  $V_{DDI} = 1.65\text{ V to }3.6\text{ V}$ ,  $GND = 0\text{ V}$ ,  $T_{OPR} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Serial communication wait time	$t_{IF}$	-	1	-	-	ms
Temperature sensor data read start time	$t_{TSEN}$	-	-	-	80	ms
Start-up time	$t_{STA}$	Output code $\pm 1\text{ }^{\circ}/\text{s}$	-	-	200	ms

- (Note) Conduct serial communication after  $t_{IF}$ .
- (Note) Conduct temperature sensor data acquisition after  $t_{TSEN}$ .
- (Note) Conduct angular rate data acquisition after  $t_{STA}$ .

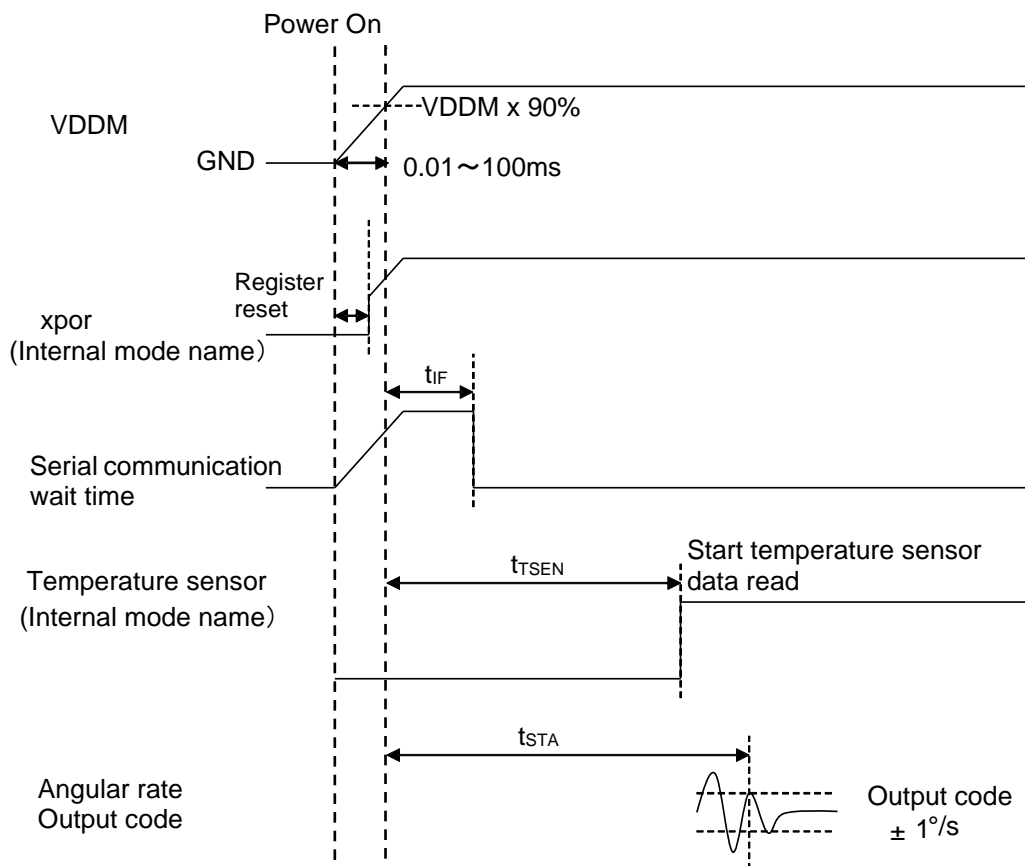


Figure 3.1 Operation Sequence at Start-up

3.5. Gyro Sensor Characteristics

**Table 3.5 Gyro Sensor Characteristics**

( $V_{DDM} = 2.7\text{ V to }3.6\text{ V}$ ,  $V_{DDI} = 1.65\text{ V to }3.6\text{ V}$ ,  $GND = 0\text{ V}$ ,  $T_{OPR} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$ )

Parameter	Symbol	Condition	Min.	Type.	Max.	Unit
Drive frequency	$F_d$	Frequency code J	50.450	51.025	51.600	kHz
Detuning frequency	$D_f$		0.7	0.9	1.1	kHz
Scale factor	$S_o$	16-bit, FS = 1 x setting		264	-	LSB/( $^{\circ}$ /s)
		16-bit, FS = 1/4 setting		66	-	
		24-bit, FS = 1 x setting		67584		
		24-bit, FS = 1/4 setting		16896		
Scale factor tolerance	$S_p$	$T_a = +25\text{ }^{\circ}\text{C}$	-2	-	+2	%
	$S_p$	$T_a = +25\text{ }^{\circ}\text{C}$ The value includes after the shipment.	-4	-	+4	%
Scale factor variation over temperature	$S_{pt}$	$V_{DDM} = 3\text{ V}$ , $T_a = +25\text{ }^{\circ}\text{C}$ reference	-3	-	+3	%
Bias	ZRL	$T_a = +25\text{ }^{\circ}\text{C}$	-	0	-	LSB
Bias variation over temperature A	$ZRL_{ta}$	$V_{DDM} = 3\text{ V}$ , $T_a = +25\text{ }^{\circ}\text{C}$ reference, $T_a = -10 \sim +50\text{ }^{\circ}\text{C}$	-0.3		+0.3	$^{\circ}$ /s
		The value includes after the shipment.	-1.3		+1.3	$^{\circ}$ /s
Bias variation over temperature B	$ZRL_{tb}$	$V_{DDM} = 3\text{ V}$ , $T_a = +25\text{ }^{\circ}\text{C}$ reference,	-1	-	+1	$^{\circ}$ /s
		The value includes after the shipment.	-2	-	+2	$^{\circ}$ /s
Bias temperature coefficient	$ZRL_s$	$V_{DDM} = 3\text{ V}$ , Average of absolute value, $\Delta T = 1\text{ }^{\circ}\text{C}$	-	0.0024	-	( $^{\circ}$ /s)/ $^{\circ}\text{C}$
Rate range	I	FS = 1 x setting	-115		+115	$^{\circ}$ /s
		FS = 1/4 setting	-460		+460	
Non-linearity	IN	$T_a = +25\text{ }^{\circ}\text{C}$	-0.25	-	+0.25	%FS
Cross-axis sensitivity	CS	$T_a = +25\text{ }^{\circ}\text{C}$	-5	-	+5	%
Current consumption	$I_{op1}$		-	1150	1400	$\mu\text{A}$
Sleep current	$I_{op3}$		-	1	30	$\mu\text{A}$
Noise density	$N_d$	@ 10 Hz, LPF default setting	-	0.0015	-	( $^{\circ}$ /s)/ $\sqrt{\text{Hz}}$
Angular random walk	N		-	0.065	-	$^{\circ}$ / $\sqrt{\text{h}}$
Bias Instability	Bs	$1\sigma$ , Bottom value of Allan Variance		0.9		$^{\circ}$ /h

3.6. Temperature Sensor Characteristics

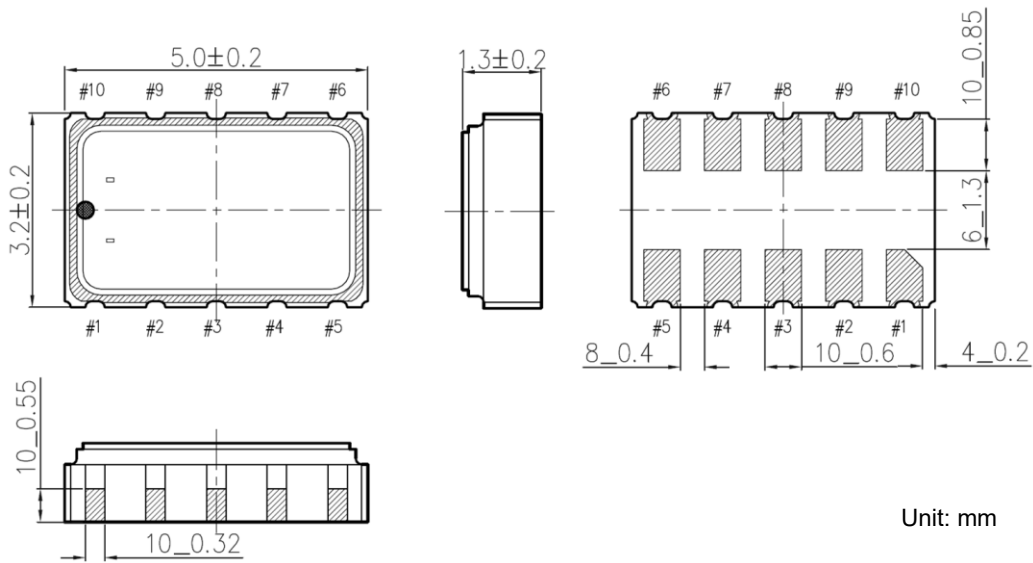
**Table 3.6 Temperature Sensor Characteristics**

( $V_{DDM} = 2.7\text{ V to }3.6\text{ V}$ ,  $V_{DDI} = 1.65\text{ V to }3.6\text{ V}$ ,  $GND = 0\text{ V}$ ,  $T_{OPR} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$ )

Parameter	Symbol	Condition	Min.	Type.	Max.	Unit
Output code	$T_{out}$	Format 1: $T_a = +25\text{ }^{\circ}\text{C}$	2560	3200	3840	LSB
		Format 2: $T_a = +25\text{ }^{\circ}\text{C}$	-1280	0	1280	
temperature error	$T_{acc}$	$T_a = +25\text{ }^{\circ}\text{C}$	-5	-	+5	$^{\circ}\text{C}$
Temperature coefficient	$T_{its}$	Format 1: $T_a = +25\text{ }^{\circ}\text{C}$	115.2	128	140.8	LSB/ $^{\circ}\text{C}$
		Format 2: $T_a = +25\text{ }^{\circ}\text{C}$	230.4	256	281.6	

## 4. Dimensions and Pin Description

### 4.1. Outline Dimensions



Unit: mm

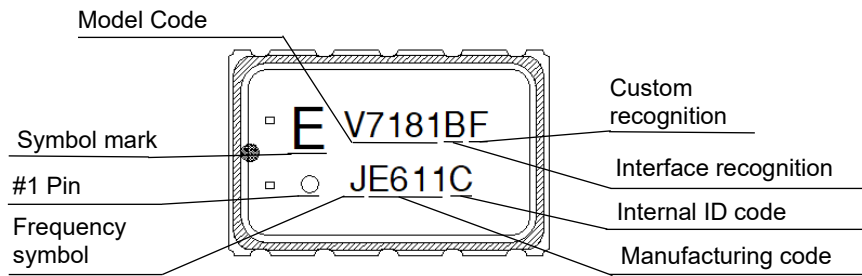
Figure 4.1 Outline Dimensions

### 4.2. Pin Name and Description

Table 4.1 Pin Name and Description

Pin number.	Pin name	Input/Output	Pin description
#1	MOSI	Input/Output	4-wire SPI communications mode: serial data input 3-wire SPI communications mode: serial data input/output I <sup>2</sup> C communications mode: serial data input/output
#2	SS	Input	4-wire SPI communications mode: slave select 3-wire SPI communications mode: slave select I <sup>2</sup> C communications mode: connect to V <sub>DDI</sub>
#3	V <sub>DDL</sub>	Output	Internal regulator voltage output Connect to the bypass capacitor 1μF
#4	Reserved1	Input	Connect to GND
#5	GND	-	GND
#6	V <sub>DDM</sub>	-	Power supply voltage
#7	Reserved2	Output	Logic "L" level output Do not connect
#8	V <sub>DDI</sub>	-	Power supply voltage for digital interface
#9	MISO	Input/Output	4-wire SPI communications mode: serial data output 3-wire SPI communications mode: Do not connect I <sup>2</sup> C communications mode: select lowest bit of slave address Default status set to pull down (approx. 100 kΩ)
#10	SCLK	Input	Serial clock (4-wire, 3-wire and I <sup>2</sup> C)

4.3. Marking Description



Frequency symbol	Drive frequency
J	51.000 kHz

Figure 4.2 Marking Discription

4.4. Pin Equivalent Circuits

An equivalent circuit for SS, SCLK, MOSI, MISO and Reserved2 is shown in Figure 4.3.

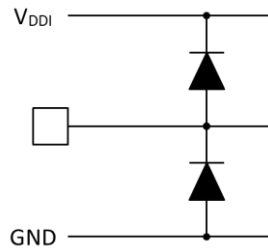


Figure 4.3 The Equivalent Circuit: SS, SCLK, MISO and Reserved2

An equivalent circuit for VDDL and Reserved1 is shown in Figure 4.4.

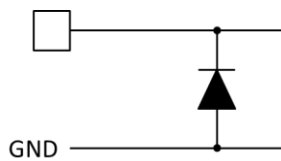


Figure 4.4 The Equivalent Circuit: VDDL and Reserved1

An equivalent circuit for VDDM and VDDI is shown in Figure 4.5.

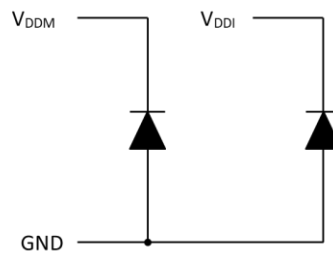
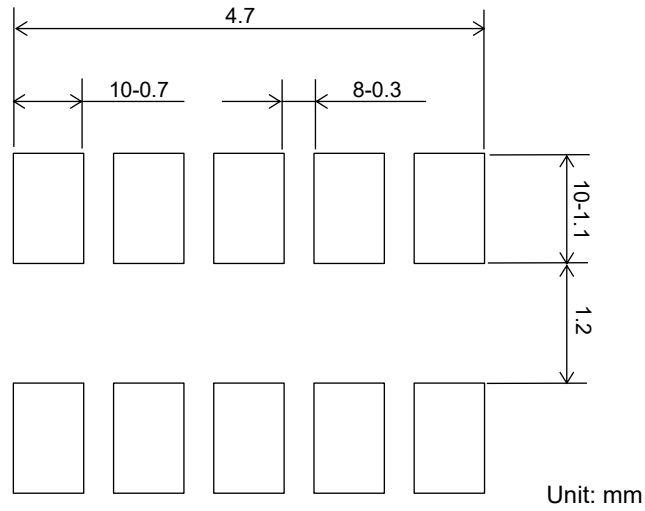


Figure 4.5 The Equivalent Circuit: VDDM and VDDI



**4.5. Soldering Pattern**

An example of a recommended soldering pattern for this product is shown in During actual board design, give due consideration to design aspects such as mounting density and solder mount reliability to ensure optimal design.



**Figure 4.6 Recommended Foot Pattern**

5. Typical Performance Characteristics

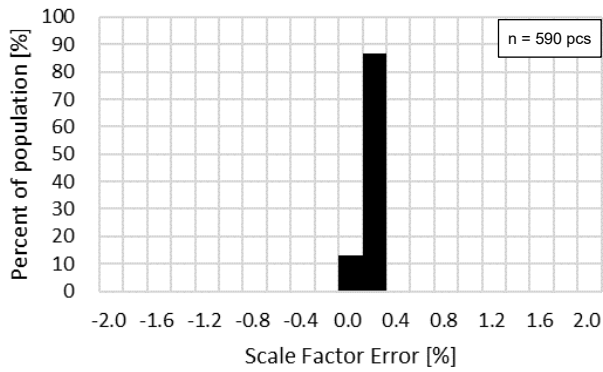


Figure 5.1 Scale Factor Tolerance at  $T_a = +25\text{ }^\circ\text{C}$

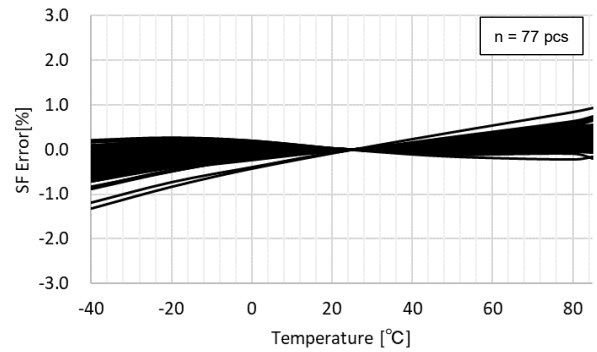


Figure 5.2 Scale Factor Variation over Temperature

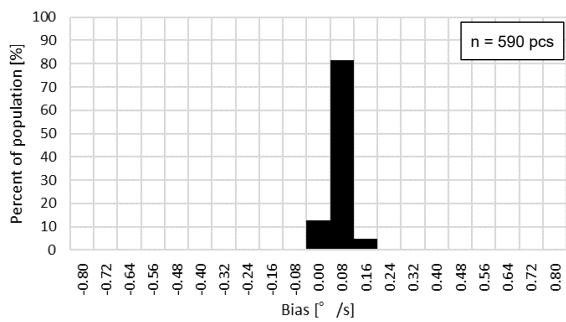


Figure 5.3 Bias Tolerance at  $T_a = +25\text{ }^\circ\text{C}$

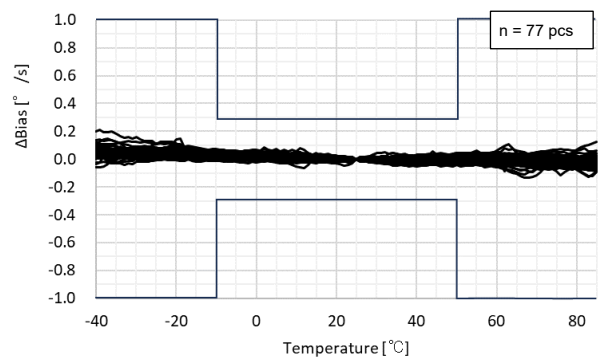


Figure 5.4 Bias Variation over Temperature

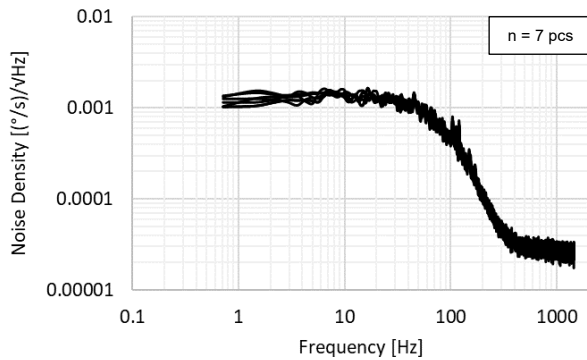


Figure 5.5 Noise Density

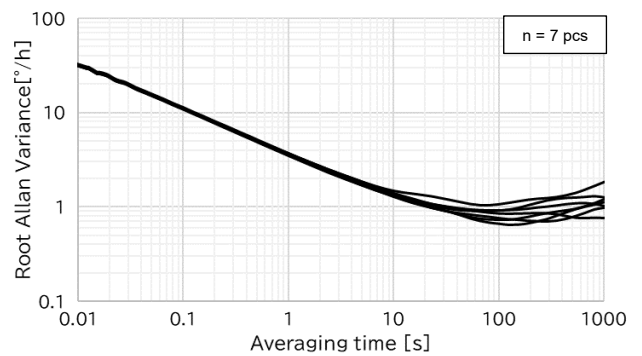


Figure 5.6 Allan Variance

## 6 Serial Interface

Access to the sensor is accomplished via serial communication. There are three methods for the serial interface: 4-wire SPI, 3-wire SPI or I<sup>2</sup>C.

4-wire SPI communication is enabled by turning on the power supply V<sub>DDM</sub>, waiting for the serial communication wait time t<sub>IF</sub> noted in Section 3.4 to elapse, and then setting the slave select (SS) to logic level "L" (refer to Section 7.12. SPISel register has a default value of "0" : 4-wire SPI). I<sup>2</sup>C communication is enabled by setting the SS to logic level "H" (refer to Section 7.12. I<sup>2</sup>C\_EN register has a default value of "1" : I<sup>2</sup>C enable). 3-wire SPI communication is enabled by setting SPISel to "1": 3-wire SPI and setting the SS to logic level "L". However, setting SPISel to "1" : 3-wire SPI will disable I<sup>2</sup>C communication.

### 6.1. 4-wire SPI

4-wire SPI communication is 8 bits width serial communication based on the SS, clock signal (SCLK), data input signal (MOSI), and data output signal (MISO). SPISel (4-wire SPI/3-wire SPI selection register) described in Section 7.12 should be set to "0" (initial value is "0": 4-wire SPI). Also, when using 4-wire SPI communication, set I<sup>2</sup>C\_EN (I<sup>2</sup>C enable register) to "0": Disable (initial value is "1": Enable).

With falling edge of SS, the initial byte becomes the address. During serial data transfer, the SS must be maintained at logic level "L." If the SS is set to logic level "H," the serial data transfer will be canceled.

The initial address bit (MSB) is the write/read control bit. Set as "0" to write data to the register and set as "1" to read data from the register.

Bits 5 (A <4:0>) on the LSB side of the address are the register address. Set the address of the register you want to access. The 2<sup>nd</sup> byte is the settings value for each register. Refer to the register map in Chapter 6 and transfer the values you want to set.

The register write sequence for 4-wire SPI is shown in Figure 6.1. Write data is transferred after the address. Maintain the SS at logic level "L" during the period between address and data transfer. During the write sequence, the MISO logic level is "L". X is "1" or "0".

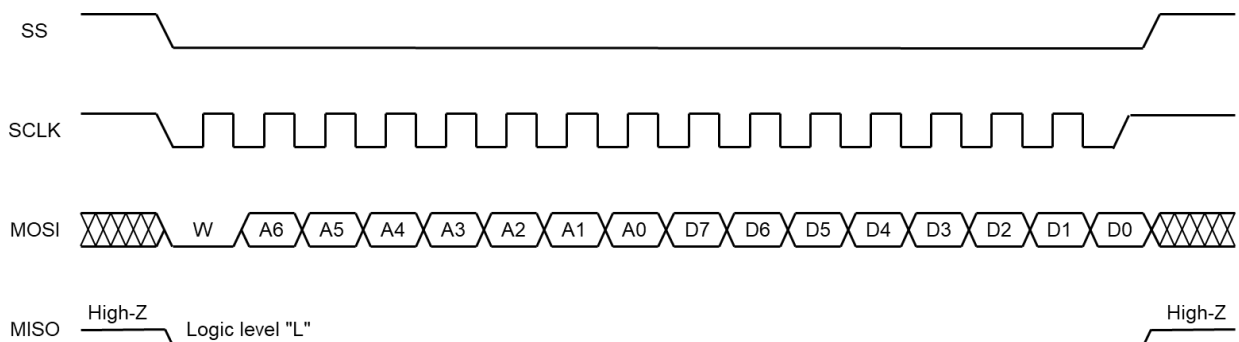


Figure 6.1 Write Sequence for 4-Wire SP

The register read sequence for 4-wire SPI is shown in Figure 6.2. After the address transfer is complete, data will simultaneously output with the SCLK falling edge beginning with the 2<sup>nd</sup> byte. Similar to the write sequence, during data non-output, the MISO logic level is "L". X is "1" or "0". Angular rate data reads are based on 16 bits output (or 24 bits output based on the angular rate data format selection indicated in Section 7.6). After reading the angular rate data from the 1<sup>st</sup> byte, maintain logic level "L" for the SS and continue clock input via the SCLK until the desired bit is read (the same applies to reading the temperature sensor data).

The sequence for only the address transfer (command) is shown in Figure 6.3. The register map indicated in Chapter 7 includes the items for only a partial address transfer (command). Similar to the register write sequence, set the first bit (MSB) of the address to "0". Bits 5 (A <4:0>) on the LSB side of the address are the register address (command). Set the address (command) you want to execute. After transferring the address (command), set the SS from logic level "L" to logic level "H" and end the serial communication. During the address transfer sequence, the MISO logic level is "L". X is "1" or "0".

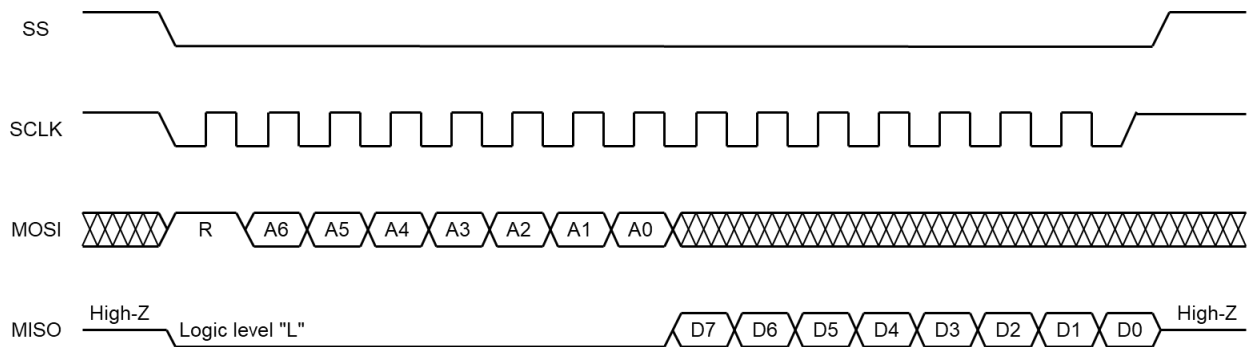


Figure 6.2 Read Sequence for 4-Wire SP

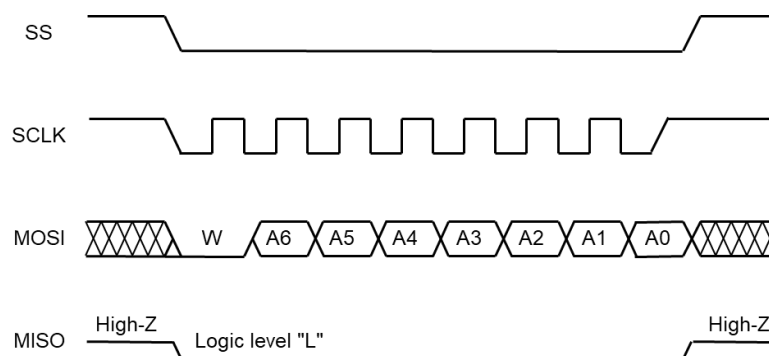


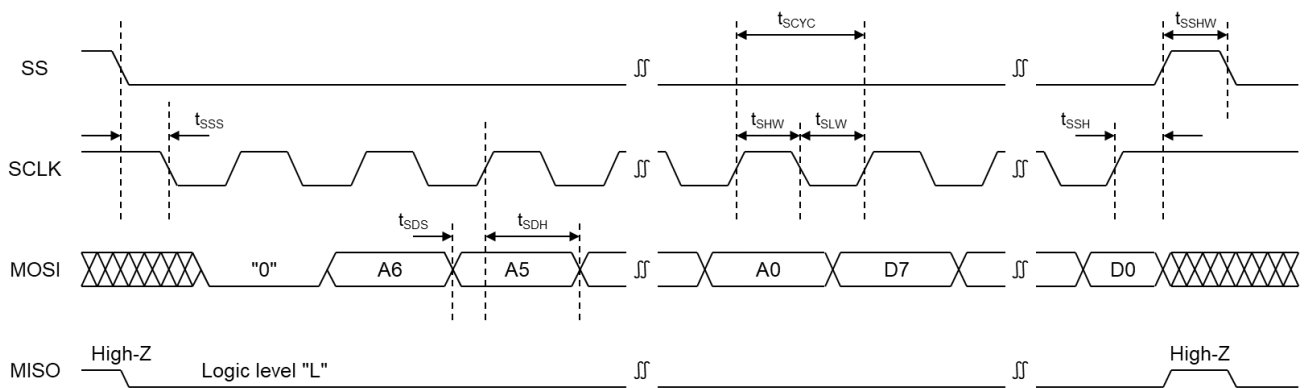
Figure 6.3 Adress Setting Sequence for 4-wire SPI

The timing diagrams for 4-wire SPI are indicated in Figure 6.4 and Figure 6.5.

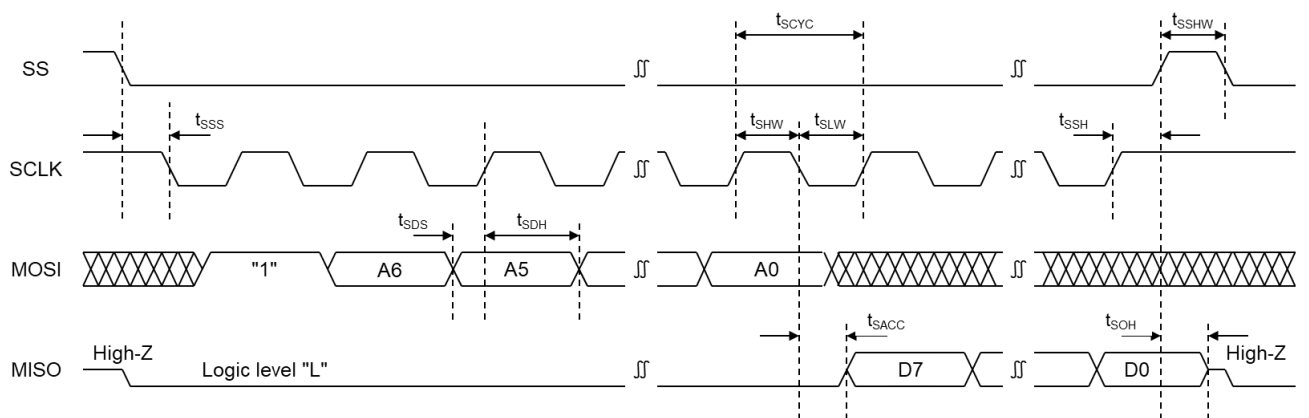
**Table 6.1 AC Characteristics for 4-Wire SPI**

( $I_{DDM} = 2.7\text{ V} \sim 3.6\text{ V}$ ,  $GND = 0\text{ V}$ ,  $T_{OPR} = -40\text{ }^{\circ}\text{C} \sim +85\text{ }^{\circ}\text{C}$ )

Parameter	Symbol	Condition	$V_{DD1} \leq 2.4\text{ V}$			$V_{DD1} > 2.4\text{ V}$			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
SS setup time	$t_{SSS}$		15	-	-	15	-	-	ns
SS hold time	$t_{SSH}$		100	-	-	100	-	-	ns
SS high pulse width	$t_{SSHW}$		30	-	-	30	-	-	ns
Clock cycle	$t_{SCYC}$		200	-	-	100	-	-	ns
Clock high pulse width	$t_{SHW}$		90	-	-	40	-	-	ns
Clock low pulse width	$t_{SLW}$		90	-	-	40	-	-	ns
Data setup time	$t_{SDS}$		10	-	-	10	-	-	ns
Data hold time	$t_{SDH}$		10	-	-	10	-	-	ns
Read access time	$t_{SACC}$	Max. $C_L = 30\text{ pF}$	-	-	80	-	-	30	ns
Output disable time	$t_{SOH}$		-	-	30	-	-	30	ns



**Figure 6.4 Timing Diagram of Writing for 4-Wire SPI**



**Figure 6.5 Timing Diagram of Reading for 4-Wire SPI**

(Note) X is "1" or "0".

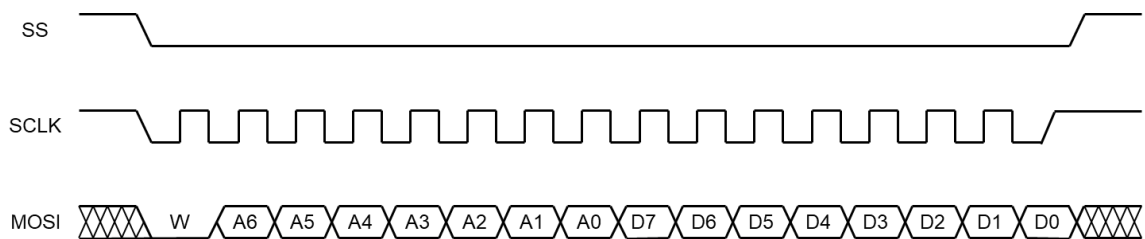
**6.2. 3-wire SPI**

The 3-wire SPI communication is 8 bits width serial communication based on the slave select signal (SS), the clock signal (SCLK), and the data input/output signal (MOSI). Set SPISel (register for selecting 3-wire SPI or 4-wire SPI) indicated in1 to "1" (the default value is "0" : 4-wire SPI). Setting SPISel to "1" will disable the I<sup>2</sup>C communication.

Like 4-wire SPI, with the falling edge of SS the initial byte becomes the address. During serial data transfer, the SS must be maintained at logic level "L". If the SS is set to logic level "H", the serial data transfer will be canceled.

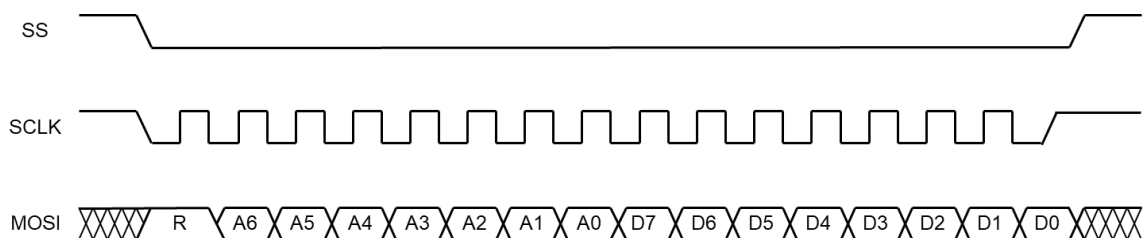
The initial address bit (MSB) is the write/read control bit. Set as "0" to write data to the register and set as "1" to read data from the register. Bits 5 (A <4:0>) on the LSB side of the address is the register address. Set the address of the register you want to access. The 2<sup>nd</sup> byte is the settings value for each register. Refer to the register map in Chapter 7 and transfer the values you want to set.

The register write sequence for 3-wire SPI is shown in Figure 6.6. Write data is transferred after the address. Maintain the SS at logic level "L" during the period between address and data transfer. X is "1" or "0."



**Figure 6.6 Write Sequence for 3-Wire SPI**

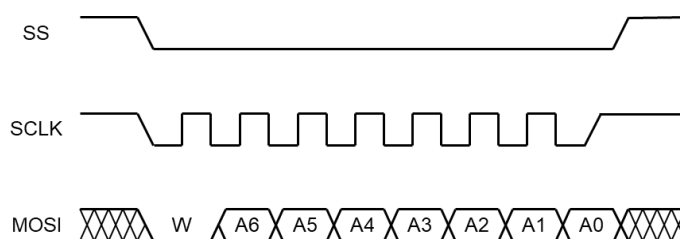
The register read sequence for 3-wire SPI is shown in Figure 6.7. After the address transfer is complete, data is simultaneously outputted with the SCLK fall beginning from the 2<sup>nd</sup> byte. Angular rate data reads are based on 16 bits output (or 24 bits output based on the angular rate data format selection indicated in Section 7.7). After reading the angular rate data from the 1<sup>st</sup> byte, maintain the SS at logic level "L" and continue clock input via the SCLK until the desired bit is read. The same applies to read the temperature sensor data. X is "1" or "0".



**Figure 6.7 Read Sequence for 3-Wire SPI**

The sequence for only the address transfer (command) is shown in Figure 6.8. The register map indicated in Chapter 7 includes the items for only a partial address transfer (command). Similar to the register write sequence, set the first bit (MSB) of the address to "0." Bits 5 (A <4:0>) on the LSB side of the address are the register address (command). Set the address (command) you want to execute. After transferring the address (command), set the SS from logic level "L" to logic level "H" and end the serial communication. X is "1" or "0."

The timing diagrams for 3-wire SPI are indicated in Figure 6.9 and Figure 6.10.



**Figure 6.8 Address Setting Sequence for 3-Wire SPI**

Table 6.2 AC Characteristics for 3-Wire SPI

$V_{DDM} = 2.7\text{ V to }3.6\text{ V}$ ,  $GND = 0\text{ V}$ ,  $T_{OPR} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$

Paramter	Symbol	Condition	$V_{DDI} \leq 2.4\text{ V}$			$V_{DDI} > 2.4\text{ V}$			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
SS setup time	$t_{SSS}$		15	-	-	15	-	-	ns
SS hold time	$t_{SSH}$		100	-	-	100	-	-	ns
SS high pulse width	$t_{SSHW}$		30	-	-	30	-	-	ns
Clock cycle	$t_{SCYC}$		200	-	-	100	-	-	ns
Clock high pulse width	$t_{SHW}$		90	-	-	40	-	-	ns
Clock low pulse width	$t_{SLW}$		90	-	-	40	-	-	ns
Data setup time	$t_{SDS}$		10	-	-	10	-	-	ns
Data hold time	$t_{SDH}$		10	-	-	10	-	-	ns
Read access time	$t_{SACC}$	Max. $C_L = 30\text{ pF}$	-	-	80	-	-	80	ns
Output disable time	$t_{SOH}$		-	-	30	-	-	30	ns

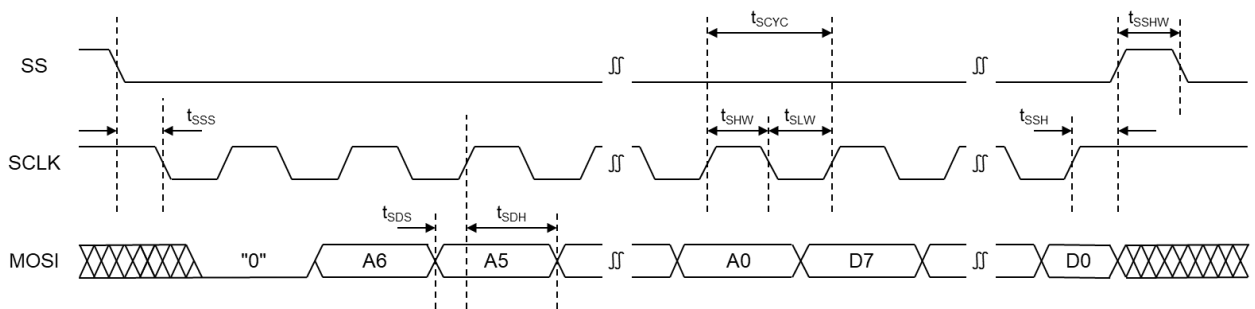


Figure 6.9 Timing Diagram of Writing for 3-Wire SPI

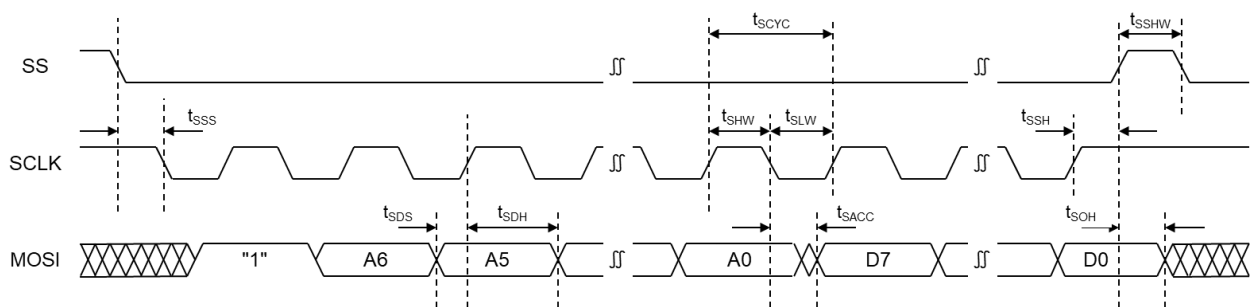


Figure 6.10 Timing Diagram of Reading for 3-Wire SPI

(Note) X is "1" or "0".

6.3. I<sup>2</sup>C

I<sup>2</sup>C communication is 8 bits width serial communication based on the clock signal (SCL) and data address signal (SDA). Set I<sup>2</sup>C\_EN (register enabling for I<sup>2</sup>C) indicated in 0) to "1" (the default value is "1" : Enable). To use I<sup>2</sup>C communication, fix the slave select signal (SS) used in 4-wire or 3-wire SPI communication to logic level "H" (interface power supply voltage V<sub>DDI</sub>).

I<sup>2</sup>C communication is initiated by issuing the start condition (ST, with SCL status at logic level "H", SDA is changed from logic level "H" to logic level "L") from the master. Or, communication is stopped by issuing the stop condition (SP, with SCL status at logic level "H", SDA is changed from logic level "L" to logic level "H") from the master.

To access the internal register, read (Read = "1") /write (Write = "0") the slave device address (ADR, address that adds the SA0 "0" or "1" to "110101") to/from the master and transmit the total 1 byte that includes 1 bit ID signal. After ADR receipt, the slave will check to see if the address matches its own address. If matching, the slave returns an ACK (acknowledge), after which communication is possible. If the address does not match, the slave returns to idle mode and waits until another ST is issued.

Internally, the SA0 terminal is set to pull down (approx. 100 kΩ). If the SA0 terminal is set to "0," then connect to N.C. or GND. Or, if the SA0 terminal is set to "1", then connect to V<sub>DDI</sub>. In this case, a current of approximately 30 μA @ V<sub>DDI</sub> = 3 V will flow to the SA0 terminal. To reduce the current, add a desired resistor to the V<sub>DDI</sub> and the SA0 terminal. Alternatively, you can change the terminal setting from pull down to pull up by rewriting the SelMISO [1:0] indicated in Section 7.11 after turning the power ON and once the serial communication wait time t<sub>IF</sub> indicated in Section 3.4 has elapsed. Refer to Section 7.11 for the setting instructions.

Next, send the internal register address (SUB-ADR). Input "0" for the first bit (MSB) of the address (there is not function allocation). The remaining LSB-side 7 bits (A <6:0> are the register address (for detail, refer to register map in Chapter 7). After transferring the address of the register you wish to access, return an ACK.

The following sequence differs between register write, register read, and address (command) transfer. Please refer to the sequences in Figure 6.11 through Figure 6.13.

Angular rate data reads are based on 16 bits output (or 24 bits output based on the angular rate data format selection indicated in Section 7.6). After reading the angular rate data from the 1<sup>st</sup> byte, set the master to return an ACK (acknowledge) instead of a NACK (non-acknowledge) and then read the 2<sup>nd</sup> byte or the 3<sup>rd</sup> byte. The same applies to read the temperature sensor data.

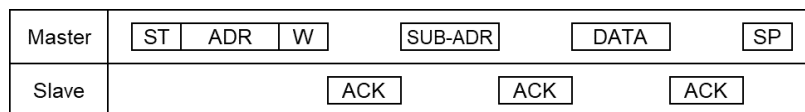


Figure 6.11 Write Protocol for I<sup>2</sup>C

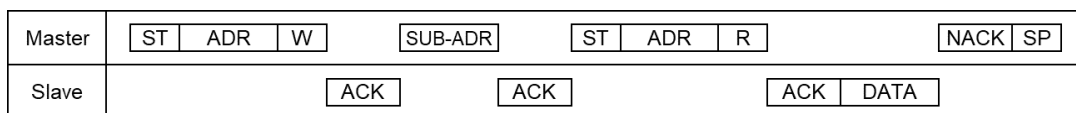


Figure 6.12 Read Protocol for I<sup>2</sup>C

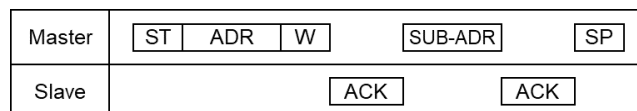
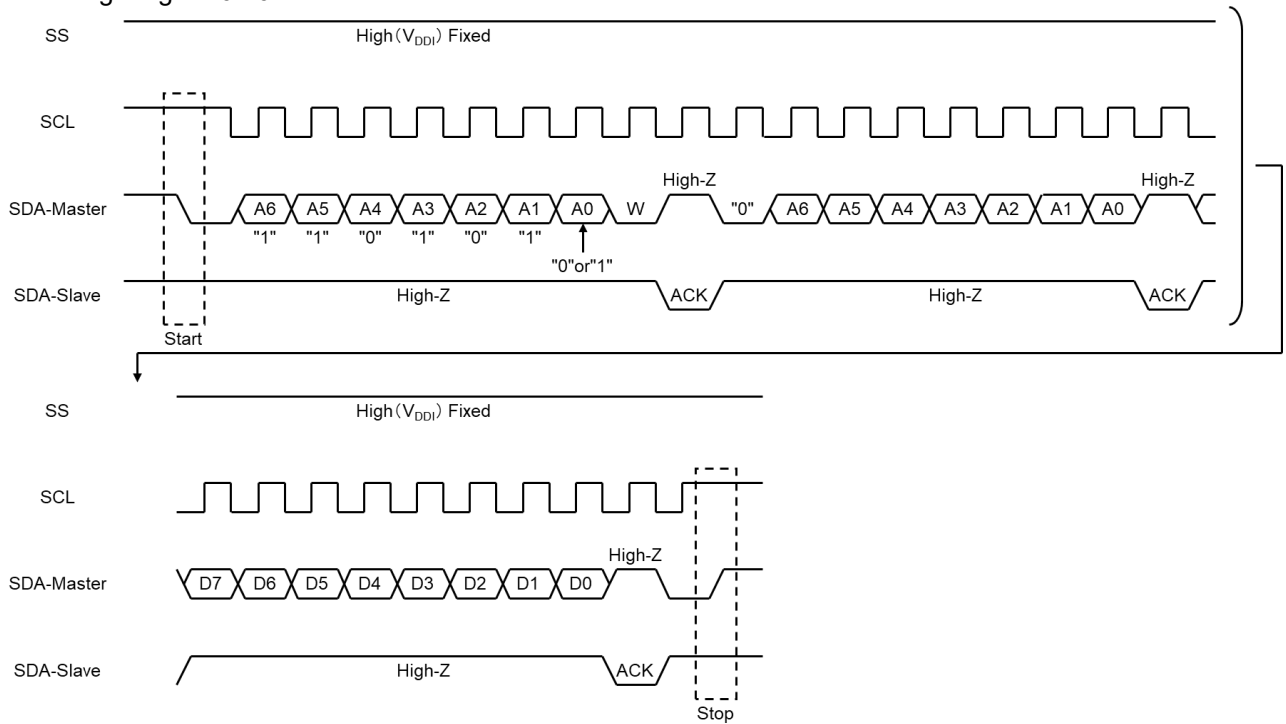


Figure 6.13 Address Setting Protocol for I<sup>2</sup>C



- ST : Start condition
- SP : Stop condition
- ADR : Slave device address (110101 + SA0)
- R/W : Read = "1", Write = "0"
- SUB-ADR : Internal register address
- DATA : Internal register read/write data
- ACK : "Low"
- NACK : "High", send at read complete.

As an example of a waveform, register write, register read, and address setting sequence are shown in Figure 6.14 through Figure 6.16.



**Figure 6.14 Write Sequence for I<sup>2</sup>C**

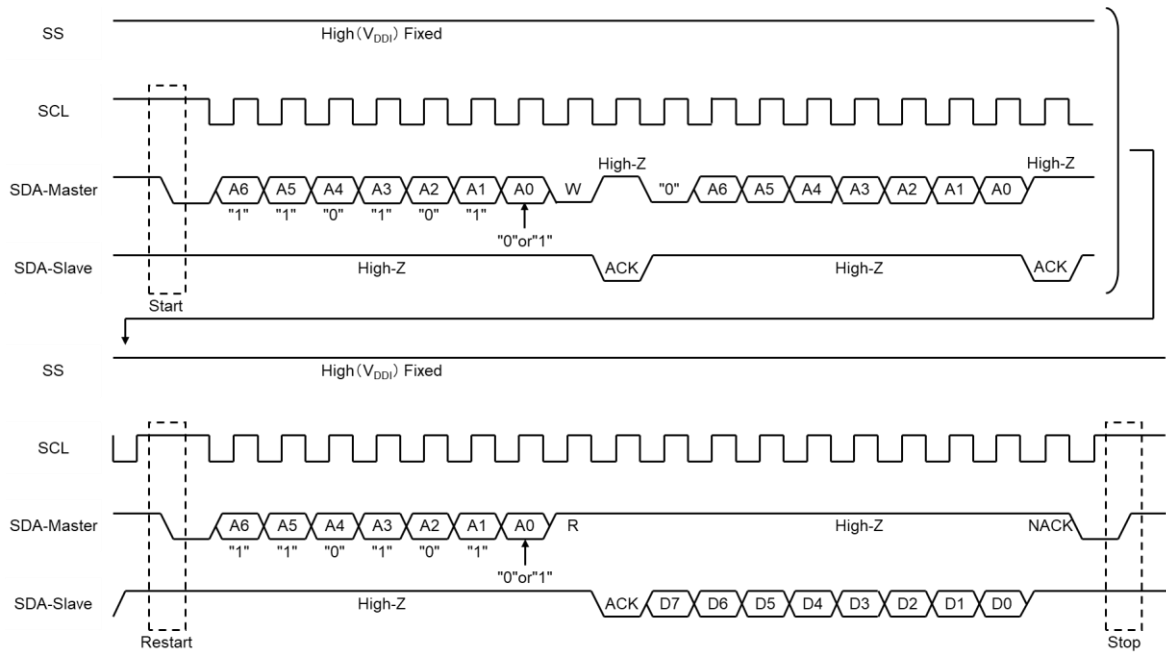


Figure 6.15 Read Sequence for I<sup>2</sup>C

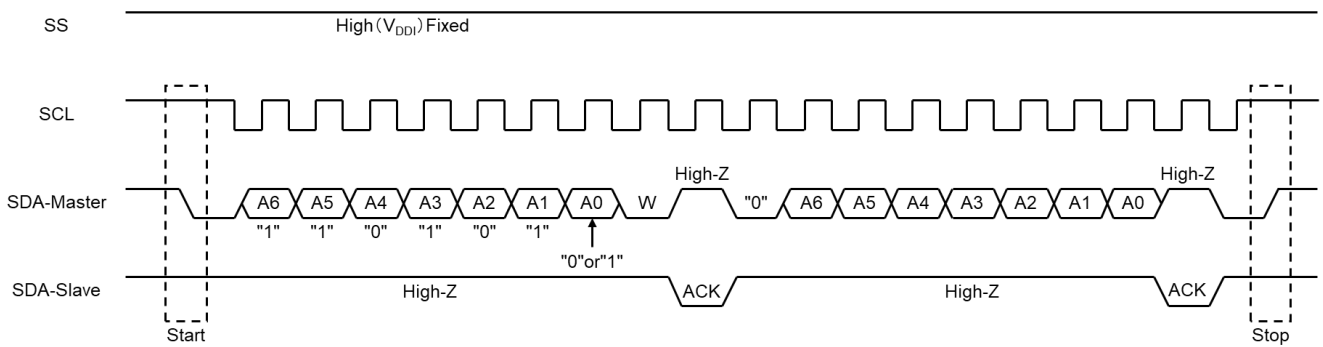


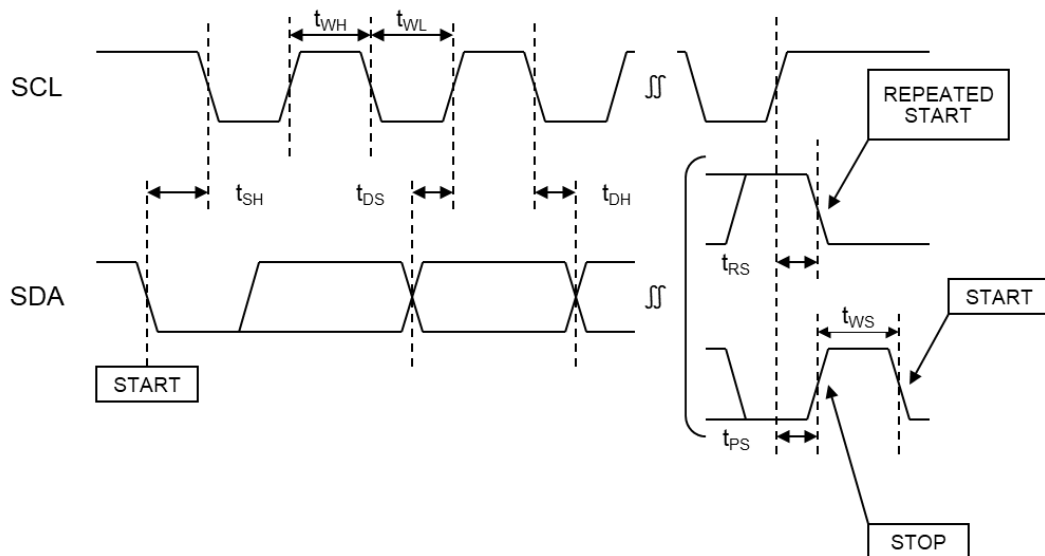
Figure 6.16 Address Setting Sequence for I<sup>2</sup>C

The timing diagram for I<sup>2</sup>C is indicated in Figure 6.17.

**Table 6.3 AC Characteristic for I<sup>2</sup>C**

$V_{DDM} = 2.7\text{ V to }3.6\text{ V, GND} = 0\text{ V, }T_{OPR} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$

Parameter	Symbol	Min.	Typ.	Max.	Unit
Clock cycle	$t_{SCL}$	2.5	-	-	$\mu\text{s}$
Clock high pulse width	$t_{WH}$	0.6	-	-	$\mu\text{s}$
Clock low pulse width	$t_{WL}$	1.3	-	-	$\mu\text{s}$
Data setup time	$t_{DS}$	0.1	-	-	$\mu\text{s}$
Data hold time	$t_{DH}$	0.0	-	-	$\mu\text{s}$
START condition hold time	$t_{SH}$	0.6	-	-	$\mu\text{s}$
Time restart condition setup time	$t_{RS}$	0.6	-	-	$\mu\text{s}$
STOP condition setup time	$t_{PS}$	0.6	-	-	$\mu\text{s}$
Between STOP and START condition	$t_{WS}$	1.3	-	-	$\mu\text{s}$



**Figure 6.17 Timing Diagram for I<sup>2</sup>C**

**6.4. Angular Rate Data Read**

The angular rate read function is conducted using the DatAccOn indicated in Table 7.1. Angular rate data uses the 2's compliment expression and has a data width of 16 bits or 24 bits (switch using the DataFormat indicated in Table 7.6).

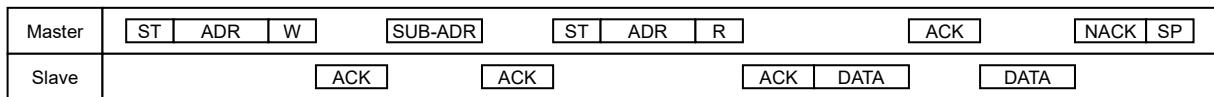
**Table 6.4 Angular Rate Data Output Control**

A [6:5]	DataFormat	Data output order		
		1 <sup>st</sup> byte	2 <sup>nd</sup> byte	3 <sup>rd</sup> byte
00	0	D [15:8]	D [7:0]	/
00	1	D [23:16]	D [15:8]	D [7:0]

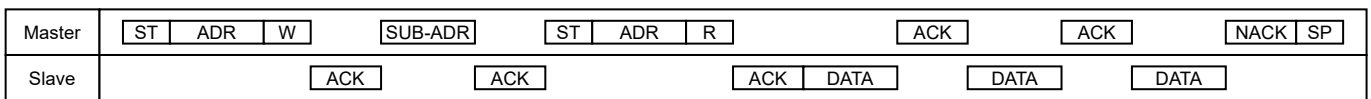
When in 4-wire SPI or 3-wire SPI communication mode, after reading the angular rate data from the 1<sup>st</sup> byte, maintain logic level "L" for the SS and continue clock input via the SCLK until the desired bit is read.

When in I<sup>2</sup>C communication mode, after reading the angular rate data from the 1<sup>st</sup> byte, set the master to return an ACK (acknowledge) instead of a NACK (non-acknowledge) and then read the 2<sup>nd</sup> byte or the 3<sup>rd</sup> byte.

**Figure 6.18 Angular Rate Data (16 Bits Output)**



**Figure 6.19 Angular Rate Data (24 Bits Output)**



**6.5. Temperature Data Read**

The temperature sensor data read is conducted using the TempRd indicated in Table 7.1. The temperature sensor data uses the 2's complement expression and has a data width of 16 bits. And you can select from the types by writing the "TFormat" in the address 0x0b of the Table 7.1. For reading, just like reading angular rate data, continue serial communication until any bit is read. Note that temperature sensor data is updated at sampling rate.

**Table 6.5 Temperature Sensor Data Output Control**

TFormat	Temperature Sensor Output	
	Sensitivity	0 Cord Temperature
0	128 LSB/°C	0 °C
1	256 LSB/°C	25 °C

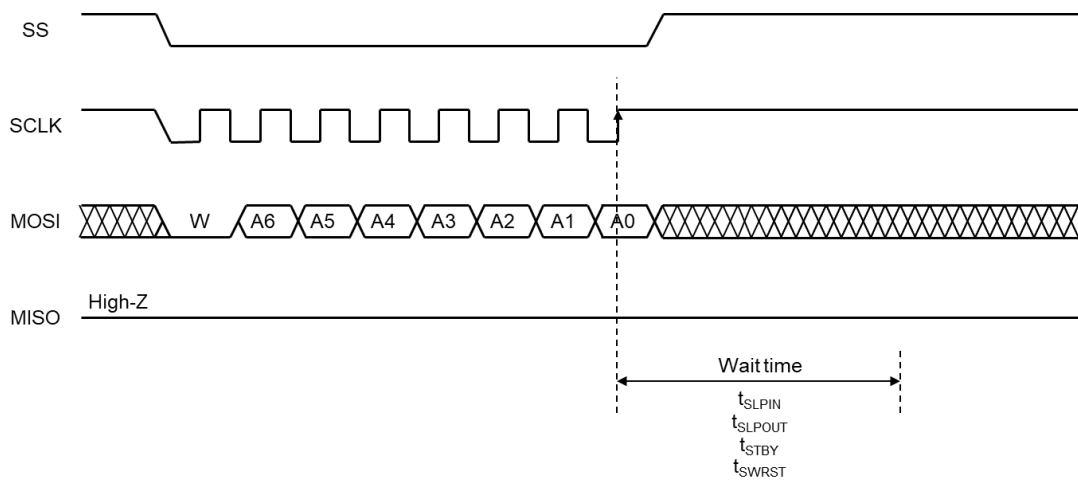
6.6. Command Validation Time

6.6.1. 4-Wire SPI, 3-Wire SPI

Table 6.6 Restriction Time for Command Issuance in SPI Communication

( $I_{DDM} = 2.7\text{ V} \sim 3.6\text{ V}$ ,  $GND = 0\text{ V}$ ,  $T_{OPR} = -40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$ )

Parameter	Symbol	Min.	Typ.	Max.	Unit
Sleep-in wait time	$t_{SLPIN}$	10	-	-	$\mu\text{s}$
Sleep-out wait time (Note 1)	$t_{SLPOUT}$	10	-	-	$\mu\text{s}$
Standby wait time	$t_{STBY}$	10	-	-	$\mu\text{s}$
Software reset wait time	$t_{SWRST}$	10	-	-	$\mu\text{s}$



( Note 1) Sleep-out command is validated after Sleep-in or Standby command issued and wait for  $t_{SLPOUT}$  or  $t_{STBY}$  to elapse.  
 (Note) X is "1" or "0".

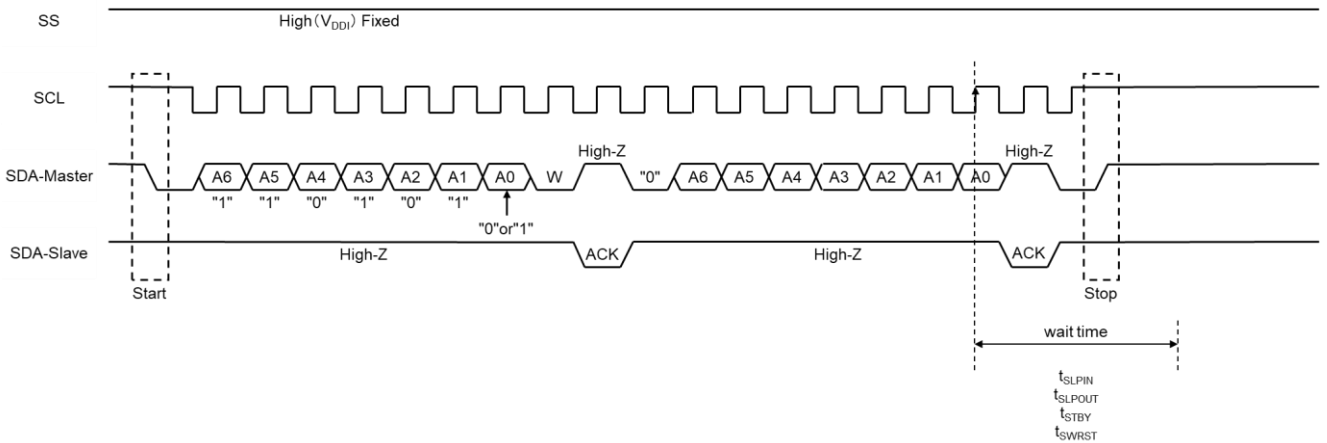
Figure 6.20 Command Validation Time for SPI

6.6.2. I<sup>2</sup>C

Table 6.7 Command Validation Time for I<sup>2</sup>C

V<sub>DDM</sub> = 2.7 to 3.6 V, GND = 0 V, T<sub>OPR</sub> = -40 °C to +85 °C

Parameter	Symbol	Min.	Typ.	Max.	Unit
Sleep-in wait time	t <sub>SLPIN</sub>	10	-	-	μs
Sleep-out wait time (Note 1)	t <sub>SLPOUT</sub>	10	-	-	μs
Standby wait time	t <sub>STBY</sub>	10	-	-	μs
Software reset wait time	t <sub>SWRST</sub>	10	-	-	μs



(Note 1) Sleep-out command is validated after Sleep-in or Standby command issued and wait for t<sub>SLPOUT</sub> or t<sub>STBY</sub> to elapse.

Figure 6.21 Command Validation Time for I<sup>2</sup>C

## 7 User Command Register

Table 7.1 User Command Register

Address	Register	Type	Function
0x00			Reserved
0x01	DspCtl1	R/W	DSP settings 1
0x02	DspCtl2	R/W	DSP settings 2
0x03			Reserved
0x04	StsRd	R	Status read
0x05	Status	R/W	Sleep-in
0x06	ProtState	R/W	Sleep-in control
0x07			Reserved
0x08	TempRd	R	Temperature sensor data read
0x09			Reserved
0x0a	DatAccOn	R	Angular rate data read
0x0b	OutCtl1	R/W	Angular rate data read control
0x0c	SelFSR	R/W	Full scale range switching
0x0d	DspRes	R/W	Digital filter reset
0x0e			Reserved
0x0f	PageSel	R/W	Page register setting
0x10			Reserved
0x11			Reserved
0x12			Reserved
0x13			Reserved
0x14			Reserved
0x15	DatLatchCom	R/W	Command data latch
0x16			Reserved
0x17			Reserved
0x18			Reserved
0x19			Reserved
0x1a	ProtSoftR	R/W	Software reset control
0x1b	SoftReset	R/W	Software reset
0x1c			Reserved
0x1d	OtCtl	R/W	MISO control
0x1e			Reserved
0x1f	IFCtl	R/W	Serial interface settings

R: Register read

R / W: Register read and register write

(Note) Reserved register must not be changed. Writing to those registers may cause permanent damage to the device.

7.1. DSP Setting 1

Table 7.2 DSP Setting 1

address	Bit	registername	initial value	Type	function	Settings
0x01	7	Reserved	0	R	Reserved	Reserved
	6	Reserved	0	R	Reserved	Reserved
	5	Reserved	0	R	Reserved	Reserved
	4	Reserved	0	R	Reserved	Reserved
	3	Reserved	0	R	Reserved	Reserved
	2	Reserved	0	R	Reserved	Reserved
	1	Reserved	0	R	Reserved	Reserved
	0	Reserved	0	R/W	Reserved	Reserved

(Note 1) When changing the setting, set the initial value except for the change bit. The settings can be changed at the same time if they are in the same register (same address).

(Note 2) Do not change the Reserved register and use the default value.

(Note 3) Do not change the RevSign register and use the default value.

7.2. DSP setting 2

Table 7.3 DSP Setting 2

Address	Bit	Register	Default	Type	function	Settings
0x02	7	Reserved	0	R	Reserved	Reserved
	6	EnbNF	0	R/IN	Notch Filter for the detune frequency	0 : Disable 1 : Enable
	5	LpfOrder[1]	0	R/W	LPF order select	LpfOrder [1:0] 00: 2 <sup>nd</sup> 01: 3 <sup>rd</sup> 10: 4 <sup>th</sup> 11: Not Available
	4	LpfOrder[0]	0	R/W		
	3	LpfFc[3]	0	R/W	LPF f <sub>c</sub> Select	LpfFc[3:0] 0000: 1Hz 0001: 10Hz 0010: 25Hz 0011: 50Hz 0100: 100Hz 0101: 200Hz 0110: 400Hz 0111: 500Hz
	2	LpfFc[2]	1	R/W		
	1	LpfFc[1]	0	R/W		
	0	LpfFc[0]	0	R/W		

(Note 1) When changing the setting, set the initial value except for the change bit. If the bits are in the same register (same address), the settings can be changed at the same time.

(Note 2) Do not change the Reserved register and use the default value.



7.3. Status Read

Table 7.4 Status Read

Address	Bit	Register	Default	Type	Function	Settings
0x04	7	Reserved	Reserved	R	Reserved	Reserved
	6	Reserved	Reserved	R	Reserved	Reserved
	5	Reserved	Reserved	R	Reserved	Reserved
	4	Reserved	Reserved	R	Reserved	Reserved
	3	Reserved	Reserved	R	Reserved	Reserved
	2	Reserved	Reserved	R	Reserved	Reserved
	1	Reserved	Reserved	R	Reserved	Reserved
	0	ProcOK	-	R	Temperature sensor Data Output flag	0: Preparing 1: Ready

7.4. Sleep In / Sleep Out Control

Sleep In is the address "0x05" of SIpIn of "0" from "1" It will be executed by. However, the Sleep In is protected. Therefore, before performing a Sleep In, the address "0x06" register "0x59" set to.

During sleep, only register access is possible. Status for angular rate data and temperature sensor data is "0". If you escape the Sleep In, the DSP is initialized.

Table 7.5 Sleep In/ Sleep Out Control

Address	Bit	Register	Default	Type	Function	Settings
0x05	7	Reserved	0	R	Reserved	Reserved
	6	Reserved	0	R	Reserved	Reserved
	5	Reserved	0	R	Reserved	Reserved
	4	Reserved	0	R	Reserved	Reserved
	3	Reserved	0	R	Reserved	Reserved
	2	Reserved	0	R	Reserved	Reserved
	1	Reserved	0	R	Reserved	Reserved
	0	SlpIn	0	R/W	Sleep In Control	0: Sleep Out 1: Sleep In
0x06	7	ProtState[7]	0	R/W	Sleep In control Enable	When 0x59 is written, SIpIn is enable.
	6	ProtState[6]	0	R/W		
	5	ProtState[5]	0	R/W		
	4	ProtState[4]	0	R/W		
	3	ProtState[3]	0	R/W		
	2	ProtState[2]	0	R/W		
	1	ProtState[1]	0	R/W		
	0	ProtState[0]	0	R/W		

7.5. Temperature Sensor Data Read

Specify address as "0x08". Only data read (no data write). Refer to Section 6.5.

7.6. Angular Rate Data Read

Specify address as "0x0a". Only data read (no data write). Refer to Section 6.4.

7.7. Angular Rate Data Read Control

Table 7.6 Angular Rate Data Read Control

Address	Bit	Register	Default	Type	Function	Settings
0x0b	7	EnblmuLatch	0	R/W	Trigger data latch function enabled (MOSI)	0: Disable 1: Enable
	6	Reserved	0	R/W	Reserved	Reserved
	5	EnbCmdTrg	0	R/W	Command data latch function enabled	0: Disable 1: Enable
	4	Reserved	0	R/W	Reserved	Reserved
	3	TFormat	0	R/W	Temperature sensor data format	0: 16bit (128 LSB/ °C) 1: 16bit (256 LSB/ °C)
	2	DataFormat	0	R/W	Angular velocity data format	0: 16bitoutput 1: 24bitoutput
	1	OutCtl[1]	0	R/W	Angular velocity data output selection	OutCtl[1:0] 00: Evaluation mode1(Note2) 01: Angular velocity data output 10: Evaluation mode2(Note2) 11: Evaluation mode3(Note2)
	0	OutCtl[0]	1	R/W		

(Note 1) When changing the setting, set the initial value except for the change bit. If the bits are in the same register (same address), the settings can be changed at the same time.

(Note 2) Do not change the Reserved register and use the default value.

7.8. Full Scale Control

You can change the full-scale range using the register at address 0x0c and set the detection range to ±115°/s or ±460°/s.

Table 7.7 Full Scale Control

Address	Bit	Register	Default	Type	function	Settings
0x0c	7	Reserved	0	R	Reserved	Reserved
	6	Reserved	0	R	Reserved	Reserved
	5	Reserved	0	R	Reserved	Reserved
	4	Reserved	0	R	Reserved	Reserved
	3	Reserved	0	R	Reserved	Reserved
	2	Reserved	0	R	Reserved	Reserved
	1	SelfFSR[1]	0	R/W	Full-scale range setting	00: FS=1 x setting 01: Reserved 10: FS=1/4 setting 11: Not set
	0	SelfFSR[0]	0	R/W		

(Note 1) When changing the setting, set the initial value except for the change bit. If the bits are in the same register (same address), the settings can be changed at the same time.

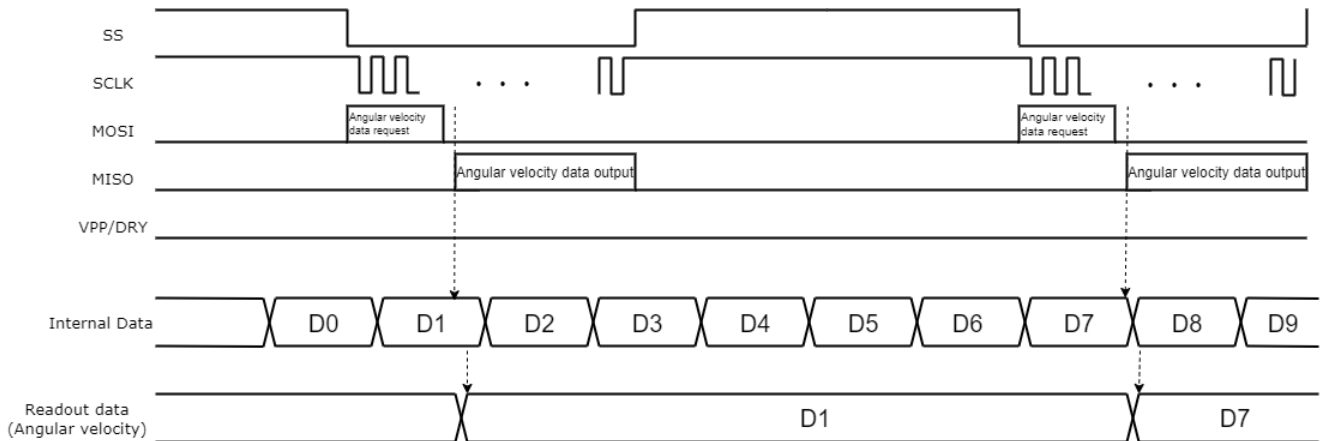
(Note 2) Do not change the Reserved register and use the default value.

**7.9. Data Latch Command Control**

The data latch function is a function that can latch the angular velocity data at any timing and read the latch data. The data latch function can be enabled by using the register with the address "0x0b" shown in Table 7.6. The trigger data latch function is enabled by setting "EnblmuLatch" to "1". Also, the command data latch function is enabled by setting "EnbCmdTrg" to "1".

It is shown in the normal angular velocity readout timing chart at Figure 7.1. When the data latch function is disabled, the data at the time when the command for reading the angular velocity request is input is output as described in Figure 7.1.

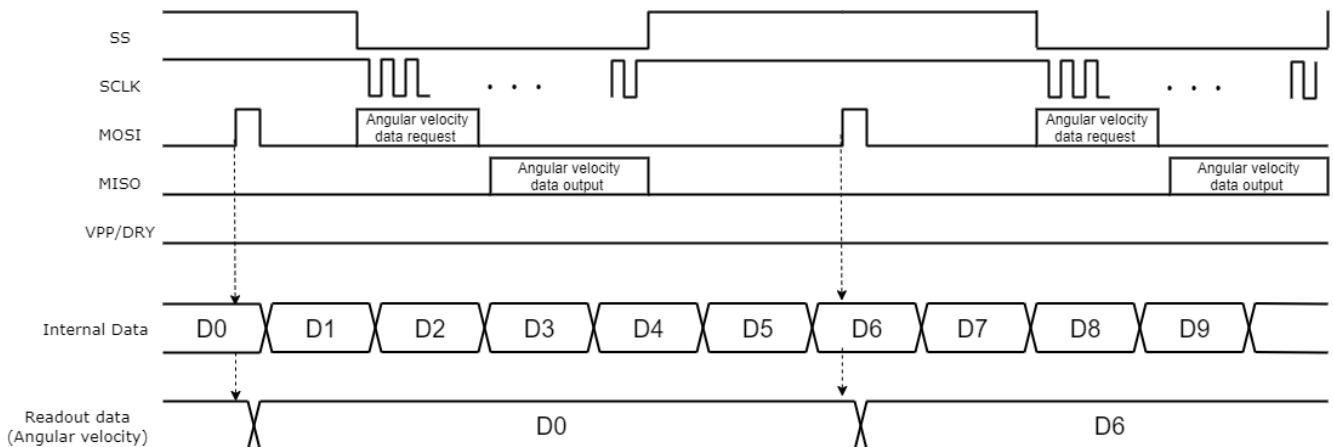
On the other hand, the data latch function latches internal data at any time using a trigger signal or command. Latch data will be read as angular velocity data in the subsequent angular velocity reading. Note that the latched read data will not be updated unless a new latch operation is performed.



**Figure 7.1 Normal Angular Rate read Timing Chart**

**7.9.1. Trigger Data Latch Function**

It is shown the timing chart of the trigger data latch function in the Figure 7.2. When the H pulse trigger signal is input to MOSI during the period of SS = H, the Internal data of the angular velocity data is latched. After the data is latched, the latched data is output when the angular velocity request is input. After that, the read data is not updated unless a new trigger signal is input.



**Figure 7.2 Trigger Data Latch Timing Chart**

※ When you use the MOSI path with other devices, this sensor recognize as the trigger pulse in the communication with other device. So, the angular velocity data is updated. Please be careful when doing so.

7.9.2. Command Data Latch Function

The command data latch function is a function to latch the internal angular rate data by setting DatLatchCom of the address "0x15" in "1"(Table 7.8). After the data is latched, the latched data is output when the angular velocity request is input. After that, the read data will not be updated unless a new latch command is executed. Therefore, if you want to latch the data again, set DatLatchCom to "0" once, and then set DatLatchCom to "1".

Table 7.8 Data Latch Command Control

Address	Bit	Register	Default	Type	Function	Settings
0x15	7	Reserved	0	R	Reserved	Reserved
	6	Reserved	0	R	Reserved	Reserved
	5	Reserved	0	R	Reserved	Reserved
	4	Reserved	0	R	Reserved	Reserved
	3	Reserved	0	R	Reserved	Reserved
	2	Reserved	0	R	Reserved	Reserved
	1	Reserved	0	R	Reserved	Reserved
	0	DatLatchCom	0	R/W	Command data latch	0→1: data latch execution

(Note 1) When changing the setting, set the initial value except for the change bit. If the bits are in the same register (same address), the settings can be changed at the same time.

(Note 2) Do not change the Reserved register and use the default value.

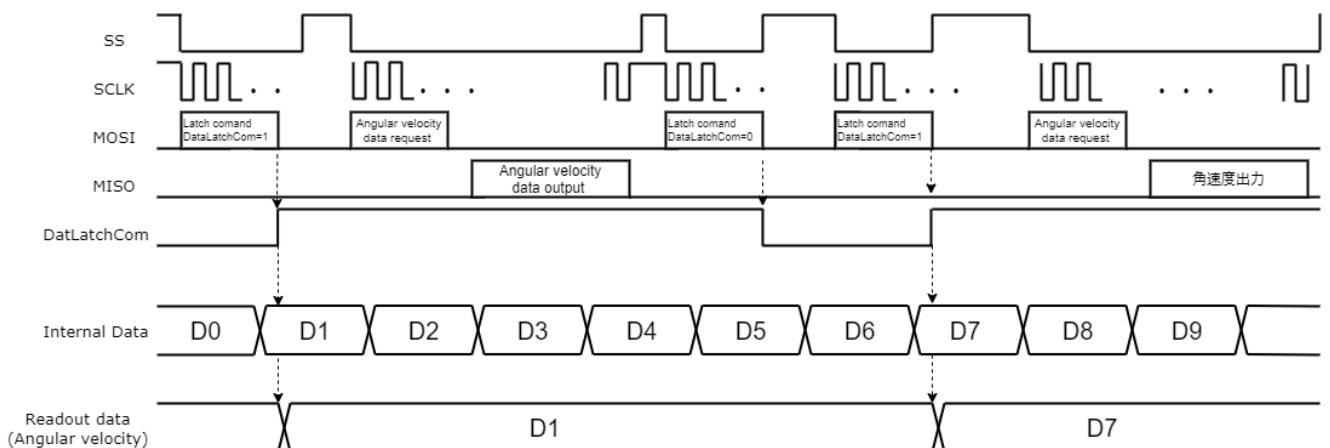


Figure 7.3 Data Command Latch Timing Chart

**7.10. Software Reset Control / Software Reset**

Software reset is the address "0x1A" of software reset of "0" from "1" It will be executed by. However, the software reset operation is protected. Therefore, before performing a software reset, the address "0x1A" register "0x59" set to.

Table at software reset the user command register shown in Table 7.1 is initialized (set to the register initial value).

**Table 7.9 Software Reset Control**

Address	Bit	Register	Default	Type	Function	Settings
0x1A	7	ProtSoftR[7]	0	R/W	Software reset enable control.	0x59 Soft resets valid
	6	ProtSoftR[6]	0	R/W		
	5	ProtSoftR[5]	0	R/W		
	4	ProtSoftR[4]	0	R/W		
	3	ProtSoftR[3]	0	R/W		
	2	ProtSoftR[2]	0	R/W		
	1	ProtSoftR[1]	0	R/W		
	0	ProtSoftR[0]	0	R/W		
0x1B	7	Reserved	0	R	Reserved	Reserved
	6	Reserved	0	R	Reserved	Reserved
	5	Reserved	0	R	Reserved	Reserved
	4	Reserved	0	R	Reserved	Reserved
	3	Reserved	0	R	Reserved	Reserved
	2	Reserved	0	R	Reserved	Reserved
	1	Reserved	0	R	Reserved	Reserved
	0	SoftReset	0	R/W	Software reset	0→1: Software reset execution

(Note 1) When changing the setting, set the initial value except for the change bit. If the bits are in the same register (same address), the settings can be changed at the same time.

(Note 2) Do not change the Reserved register and use the default value.

**7.11. MISO / SA0 Pin Control**

The MISO / SA0 Pin Control is the address "0x1d" in the Table.7.1. The MISO / SA0 Output is changed by writing the "SelMISO[1:0]". The pin condition is shown in the table. 7.10.

**Table 7.10 Control of the MISO/SA0 pin**

Address	Bit	Register	Default	Type	Function	Settings
0x1d	7	Reserved	0	R	Reserved	Reserved
	6	Reserved	0	R	Reserved	Reserved
	5	Reserved	0	R	Reserved	Reserved
	4	Reserved	0	R	Reserved	Reserved
	3	Reserved	0	R	Reserved	Reserved
	2	Reserved	0	R	Reserved	Reserved
	1	SelMISO[1]	1	R/W	MISO/SA0 pin Status select	(Note 1)
	0	SelMISO[0]	0	R/W		

(Note 1) Refer to the Table 7.11. Condition of the MISO/SA0 Pin Control.

(Note 2) Do not change the Reserved register and use the default value.

**Table 7.11 Condition of the MISO/SA0 Pin Control.**

Mode	SPISel	SelMISO[1]	SelMISO[0]	SS	MISO/SA0
4-wire SPI	0 (4-wire SPI)	X	X	0	Output
	0	0	0	1	Output "L" level
	0	0	1	1	Output "H" level
	0	1	X	1	High-Z
3-wire SPI	1 (3-wire SPI)	0	0	X	Output "L" level
	1	0	1	X	Output "H" level
	1	1	X	X	High-Z

(Note 1) Initial value is "1" in the SelMISO[1] and it is "0" in the SelMISO[0].

(Note 2) In case of the readings the pin outputs, in the other status it is High-Z.

(Note 3) SA0 is fixed "Low" in the IC internal.

### 7.12. Serial Interface Settings

The interface can be selected by setting the register "SPISel" (4-wire SPI/3-wire SPI selection register) and "I<sup>2</sup>C\_EN" at address 0x1f listed in Table 7.1. In the default setting, 4-wire SPI communication is possible when SS is L, and I<sup>2</sup>C communication is possible when SS is H. However, there is a possibility of malfunction, so when using SPI communication, it is recommended that the register "I<sup>2</sup>C\_EN" be set to "0" (initial value is "1": enable).

**Table 7.12 Serial Interface Settings**

Address	Bit	Register	Default	Type	Function	Settings
0x1f	7	Reserved	0	R	Reserved	Reserved
	6	Reserved	0	R	Reserved	Reserved
	5	Reserved	0	R	Reserved	Reserved
	4	Reserved	0	R	Reserved	Reserved
	3	Reserved	0	R	Reserved	Reserved
	2	Reserved	0	R	Reserved	Reserved
	1	SPISel (Note 3)	0	R/W	4-wire/3-wire SPI select	0: 4-wire SPI 1: 3-wire SPI
	0	I <sup>2</sup> C_EN (Note 3)	1	R/W	I <sup>2</sup> C enable	0: Disable 1: Enable

(Note 1) When changing the setting, set the initial value except for the change bit. If the bits are in the same register (same address), the settings can be changed at the same time.

(Note 2) The mode indicated in Table 7.12 can be changed only by SPI communication.

(Note 3) Reserved register must not be changed. Use the default settings.

## 8 Filter Characteristics

### 8.1. Digital Filter

In this product you can choose the filter setting in the “Selectable digital Low-Pass Filter (LPF)”.

#### 8.1.1. Selectable digital Low-Pass Filter (LPF)

The typical characteristic values of the selectable digital LPF are shown in Table 8.1. And the bode plots of them are shown in Figure 8.1 to Figure 8.3. The digital LPF has selectable filter orders (2<sup>nd</sup>, 3<sup>rd</sup> and 4<sup>th</sup> order) and cutoff frequencies (1Hz to 500 Hz). Refer to Section 7.2 for the setting instructions.

**Table 8.1 Selectable Digital LPF**

Parameter	Condition		Type.			Unit
	LpfFc [3:0]	f <sub>c</sub>	2nd order	3rd order	4st order	
Phase @ 10 Hz	0000	1 Hz	-164.6	-240.7	-314.1	°
	0001	10 Hz	-65.5	-80.8	-94.0	°
	0010	25 Hz	-28.7	-34.5	-39.3	°
	0011	50 Hz	-14.6	-17.3	-19.8	°
	0100	100 Hz	-7.3	-8.7	-9.9	°
	0101	200 Hz	-3.7	-4.3	-4.9	°
	0110	400 Hz	-1.8	-2.2	-2.5	°
	0111	500 Hz	-1.5	-1.7	-2.0	°
Group delay @ DC	0000	1 Hz	239.7	280.6	318.5	ms
	0001	10 Hz	20.7	24.5	27.9	ms
	0010	25 Hz	8.2	9.8	11.1	ms
	0011	50 Hz	4.1	4.9	5.6	ms
	0100	100 Hz	2.1	2.4	2.8	ms
	0101	200 Hz	1.0	1.2	1.4	ms
	0110	400 Hz	0.5	0.6	0.7	ms
	0111	500 Hz	0.4	0.5	0.6	ms



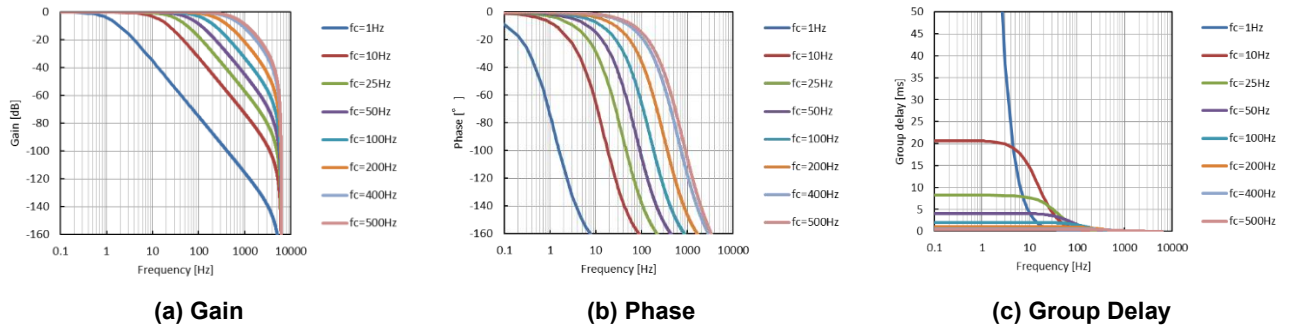


Figure 8.1 Bode plots of the Selectable Digital LPF(2nd)

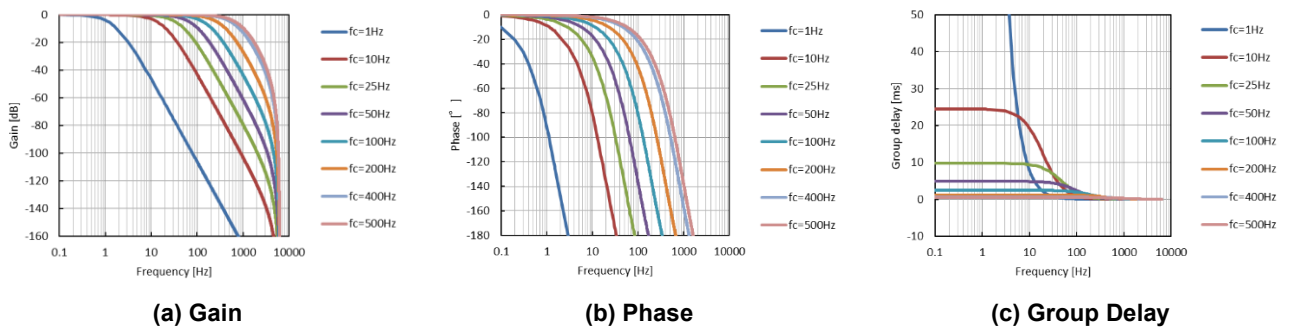


Figure 8.2 Bode plots of the Selectable Digital LPF(3rd)

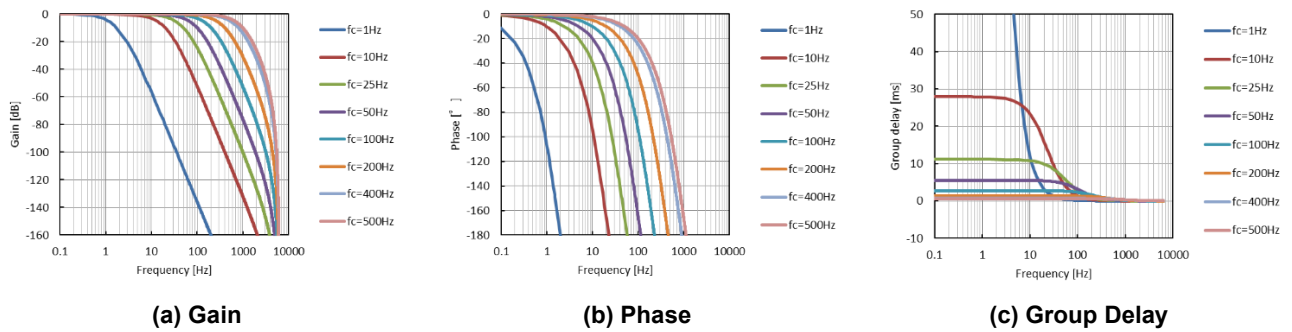


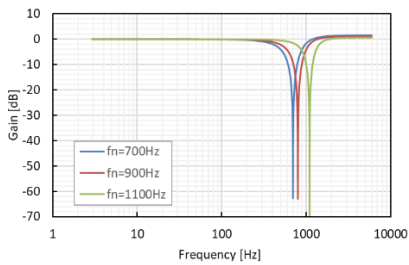
Figure 8.3 Bode plots of the Selectable Digital LPF(4th)

8.1.2. Notch Filter (NF)

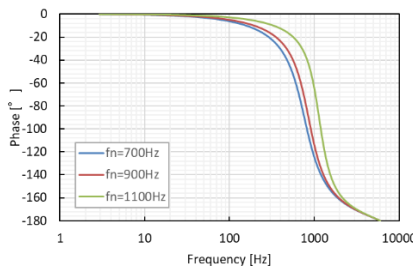
The Notch Filter is used to remove the detuned frequency component (see section 12.3). As the center frequency  $f_n$  (700 Hz to 1100 Hz) of the filter is set at the factory individually, it cannot be changed. And it is possible to select whether enable or disable the Notch Filter. The characteristic of the Notch Filter is shown in the Table 8.2 and Figure 8.4. Please refer to Section 7.2 for the setting instructions.

**Table 8.2 Characteristic of the Notch Filter (NF)**

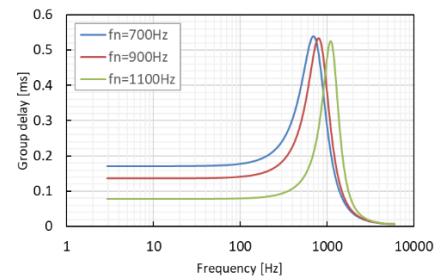
Item	Condition	Typ.	Unit
	$f_n$		
Phase@ 10 Hz	700 Hz	-0.63	°
	900 Hz	-0.50	°
	1100 Hz	-0.29	°
Group Delay@ 10 Hz	700 Hz	0.17	ms
	900 Hz	0.14	ms
	1100 Hz	0.08	ms



**(a) Gain**



**(b) Phase**



**(c) Group Delay**

**Figure 8.4 Bode plots of the Notch Filter (NF)**

## 9 Connection Diagram

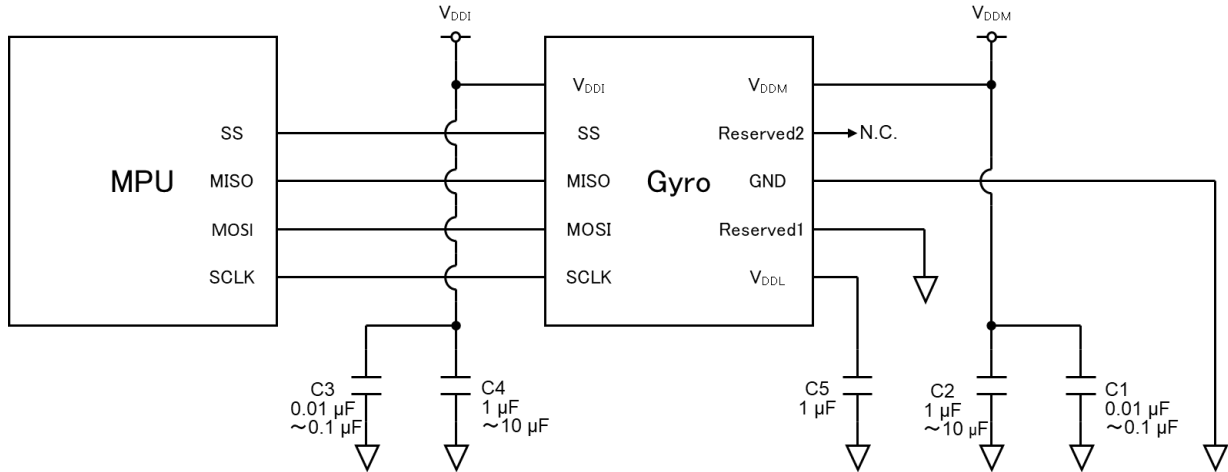


Figure 9.1 Example of 4-Wire SPI Connection

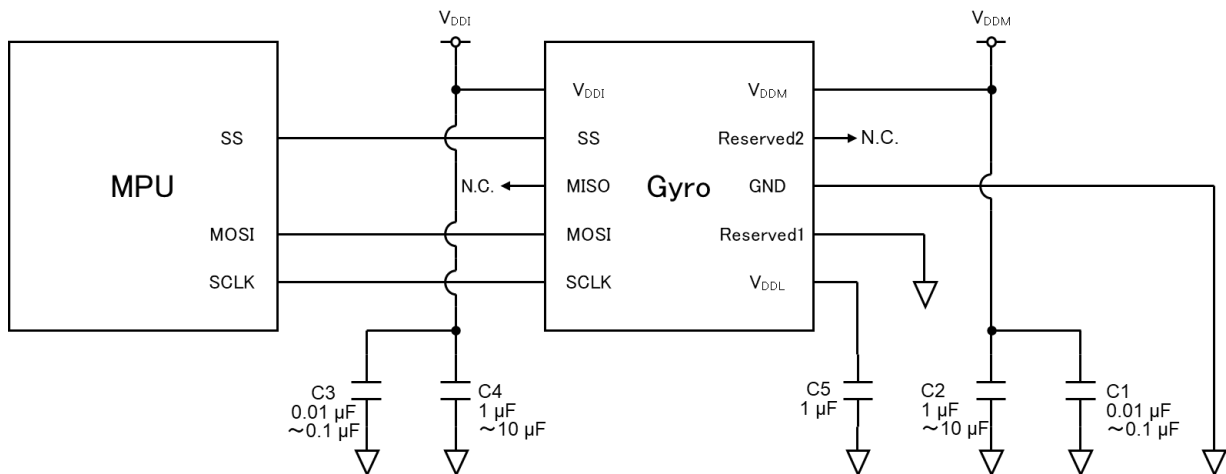


Figure 9.2 Example of 3-Wire SPI Connection

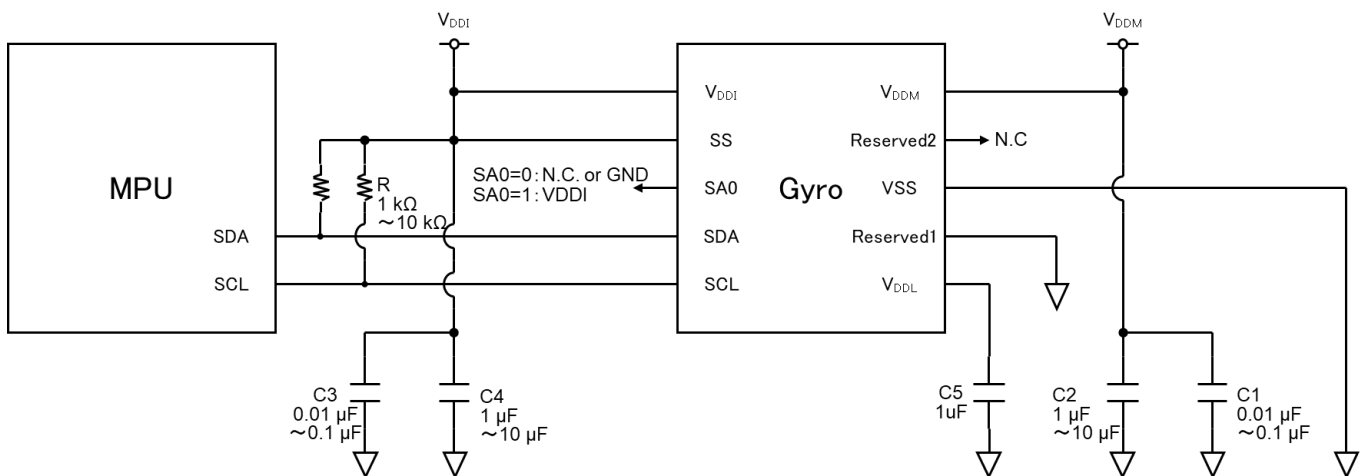


Figure 9.3 Example of I<sup>2</sup>C Connection

## 10 Other information

### 10.1. Moisture Sensitivity Level (MSL)

Table 10.1 MSL

Parameter	Level	Standard
MSL	1	JEDEC J-SD-020D.01

### 10.2. Electro-Static Discharge (ESD)

Table 10.2 ESD

Model	Min.	Standard & Condition
HBM	2000 V	JESD22-A114, V <sub>DDM</sub> , V <sub>DDI</sub> and GND reference, 3 times
MM	200 V	JESD22-A115, V <sub>DDM</sub> , V <sub>DDI</sub> and GND reference, 1 time

### 10.3. Soldering Profile

A solder heat resistance of this product was verified under the air reflow soldering profile (JEDEC J-STD-020D.1) shown in Figure 10.1.

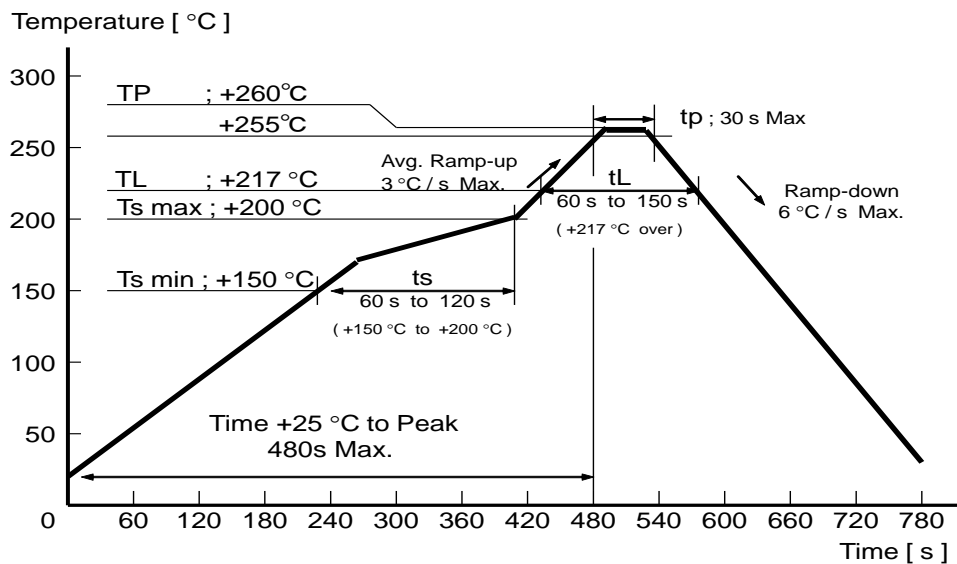


Figure 10.1 Soldering Profile

## 11 Taping Information

### 11.1. Taping Quantity

The standard quantity in a reel is 2000 pcs.

### 11.2. Taping Specification

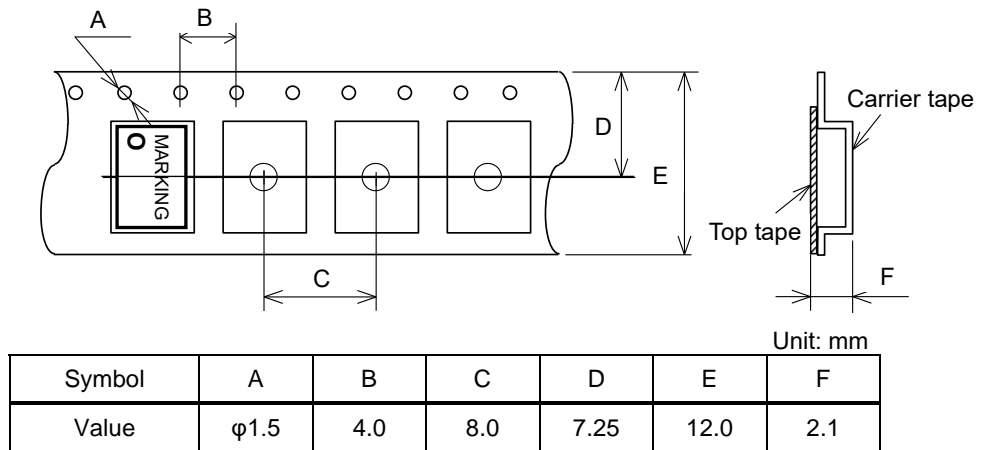
Subject to EIA-481, IEC 60286, JIS C0806.

**Table 11.1 Tape and Reel Materials**

Item	Material
Carrier tape	Black conductive PS (polystyrene)
Top tape	Antistatic PET (polyethylene terephthalate)
Reel	Black conductive PS

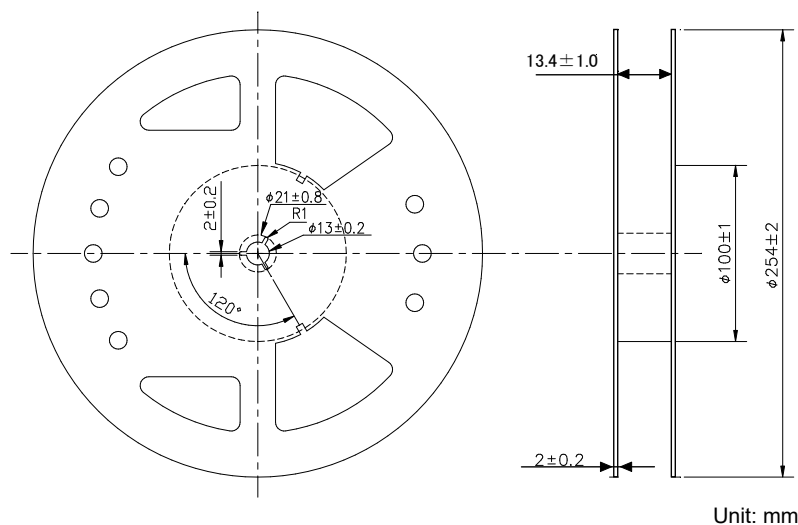
### 11.3. Taping Dimension

Subject to EIA-481, IEC 60286, JIS C0806.



**Figure 11.1 Tape Dimensions**

### 11.4. Reel Dimension



**Figure 11.2 Reel Dimensions**

## 12 Terminology

### 12.1. Cross Axis Sensitivity

The value is derived by dividing sensitivity around the X and Y axis by the sensitivity around the Z axis. The X, Y, and Z axis directions are as shown in Figure 12.1.

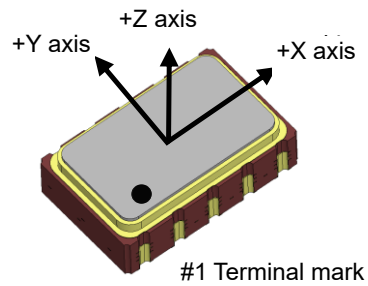


Figure 12.1 Each axis detection

### 12.2. Drive Frequency

The drive frequency is the resonance frequency (drive mode) of the sensor element continuously vibrated to gain the Coriolis force.

### 12.3. Detuning Frequency

The detuning frequency is the natural frequency used for the mechanical-electrical transduction of the Coriolis force. It is the difference from the drive frequency.

## 13 Handling Precaution

**Crystal devices are high precision products. Use the following precautions during handling.**

- 1) The detuning frequency for this product is Typ 900Hz. During board design, the customer must ensure that the board resonance frequency is not within the vicinity of this detuning frequency. When mounting on a board, align the sensor near a board loading component with low resonance variation.
- 2) Excessive shock from adsorption/chucking when mounting the sensor or excessive vibration or shock during board cutting or an impact wrench after mounting can result in damage to the sensor or the deterioration of sensor properties. Establish conditions that avoid vibration or shock to the sensor to ensure there is not loss in performance.
- 3) To detect angular rate, this product uses a drive frequency to drive the sensor element. External application of a signal with frequency components in the vicinity of the drive frequency or high-order harmonics can result in fluctuations in angular rate output by the sensor. Be sure to confirm internally in advance concerning power supply decoupling measures and serial interface communications frequency settings.
- 4) To prevent malfunctions caused by electromagnetic induction and static induction from other signal lines, during pattern design do not pass other signal lines near the sensor or along the back of the package. Also, use a pattern design that does not cross with other signal lines.
- 5) It may occur communication error with the device due to the signal pattern of board. In that case, please connect dumping resistor to reduce noise/overshoot/undershoot of the signal.
- 6) Confirm internally in advance concerning measures for vibration, shock, and noise.
- 7) This product design incorporates shock resistance but there is the risk of product damage due to drops and shock.  
**Do not use this product if it has been dropped as we cannot guarantee product performance.**
- 8) Applying ultrasonic vibration during ultrasonic washing can cause resonance damage to the crystal unit depending on usage conditions. As we cannot specify the usage conditions (washer type, power, time, tub position, etc.) at your company, we offer no guarantees concerning operability after the application of ultrasonic vibration. Confirm internally prior to use if the use of ultrasonic washing is required.
- 9) Prior to use, conduct mounting tests internally to confirm there is no impact on performance. Similarly, confirm prior to changing any conditions. During and after mounting, ensure that the sensor is not in contact with boards or structural elements.
- 10) The sensor includes a static electricity protection circuit, but application of significant static electricity can result in damage to the sensor's internal IC. Make sure to use conductive materials for packaging and transport containers as well. For the soldering iron, measurement circuit, etc., use products with no high-voltage leaks and during mounting make sure to employ static electricity measures such as the use of a ground wire.
- 11) Keep reflow to no more than three times. Use a soldering iron to correct any soldering mistakes. Here, the temperature of the iron type should be below +350 °C and less than 3 seconds. (Blower use not allowed)
- 12) We recommend using board production based on Epson pad dimensions.
- 13) This product has the same frequency noise as drive frequency. Remove using an appropriate filter circuit.
- 14) This product is designed to resist acoustic interference even when multiple sensors are operated in close proximity but impedance common to board resonance and power supply could result in mechanical or electrical interference. Confirm internally prior to use.
- 15) This product includes a POR circuit. To avoid the POR circuit malfunctions, power supply voltage rise should be conducted between 0.01 ms and 100 ms.
- 16) Do not use in high condensation or other environments prone to short circuits between terminals.
- 17) Using the drive frequency integral multiplier as communications clock may result in fluctuations in the angular rate output.
- 18) Acquiring angular rate data as a frequency that is a fraction of the integer for the drive frequency can result in fluctuations in the angular rate output.

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